

RX140 Group, RX111 Group

Differences Between the RX140 Group and the RX111 Group

Introduction

This application note is intended as a reference to points of difference between the peripheral functions, I/O registers, and pin functions of the RX140 Group and RX111 Group, as well as a guide to key points to consider when migrating between the two groups.

Unless specifically otherwise noted, the information in this application note applies to the 80-pin package version of the RX140 Group and the 64-pin package version of the RX111 Group as the maximum specifications. To confirm details of differences in the specifications of the electrical characteristics, usage notes, and setting procedures, refer to the User's Manual: Hardware of the products in question.

Target Devices

RX140 Group and RX111 Group

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1. Comparison of Built-In Functions of RX140 Group and RX111 Group

A comparison of the built-in functions of the RX140 Group and RX111 Group is provided below. For details of the functions, see section 2, Comparative Overview of Specifications and section 5, Reference Documents.

Table 1.1 is a comparison of built-in functions of RX140 Group and RX111 Group.

Table 1-1 Comparison of Built-In Functions of RX140 Group and RX111 Group

Function	RX111	RX140		
<u>CPU</u>		•		
Operating modes		•		
Address space		•		
Resets		•		
Option-setting memory (OFSM)		/=		
Voltage detection circuit (LVDAa): RX111, (LVDAb): RX140)/▲		
Clock generation circuit)/▲		
Clock frequency accuracy measurement circuit (CAC)		0		
Low power consumption	•/	A /		
Register write protection function)/▲		
Exception handling)/▲		
Interrupt controller (ICUb)		<u> </u>		
Buses		<u> </u>		
Data transfer controller (DTCa): RX111, (DTCb): RX140		•		
Event link controller (ELC))/ A		
I/O ports)/ =		
Multi-function pin controller (MPC)		<u>/</u>		
Multi-function timer pulse unit 2 (MTU2a)		0		
Port output enable 2 (POE2a)		Ö		
8-bit timer (TMRa)	X			
Compare match timer (CMT)		Ó		
Realtime clock (RTCA): RX111, (RTCB): RX140				
Low-power timer (LPTa)	X	0		
Independent watchdog timer (IWDTa)		Ó		
USB 2.0 Host/Function Module (USBc)	0	×		
Serial communications interface (SCIe, SCIf): RX111,)/▲		
(SClg*1, SClk, SClh): RX140				
I ² C bus interface (RIIC): RX111, (RIICa): RX140				
CAN module (RSCAN0)	X	O*1		
Serial peripheral interface (RSPI): RX111, (RSPIc): RX140)/▲		
CRC calculator (CRC)		<u> </u>		
Capacitive touch sensing unit (CTSU2SL,CTSU2L)	X	0		
AESA	X	0		
RNGA	X			
12-bit A/D converter (S12ADb): RX111, (S12ADE): RX140)/▲		
D/A converter (DA):RX111, (DAa):RX140)/▲		
Temperature sensor (TEMPSA)				
Comparator B (CMPBa)	X			
Data operation circuit (DOC)		<u> </u>		
RAM				

Function	RX111	RX140
Flash memory (FLASH)	•/4	/=
<u>Packages</u>	•/	/

^{○:} Available, ×: Unavailable, •: Differs due to added functionality,

Note: 1. Not implemented on products with ROM capacity of 64 KB.

^{▲:} Differs due to change in functionality, ■: Differs due to removed functionality.

2. Comparative Overview of Specifications

This section presents a comparative overview of specifications, including registers.

In the comparative overview, red text indicates functions which are included only in one of the MCU groups and also functions for which the specifications differ between the two groups.

In the register comparison, red text indicates differences in specifications for registers that are included in both groups and **black text** indicates registers which are included only in one of the MCU groups. Differences in register specifications are not listed.

2.1 CPU

Table 2.1 is a comparative overview of CPU, and Table 2.2 is a comparison of CPU registers.

Table 2-1 Comparative Overview of CPU

Item	RX111	RX140
CPU	Maximum operating frequency: 32 MHz	Maximum operating frequency: 48 MHz
	32-bit RX CPU	32-bit RX CPU (RXv2)
	Minimum instruction execution time:	Minimum instruction execution time:
	One instruction per clock cycle	One instruction per clock cycle
	Address space: 4 GB, linear	Address space: 4 GB, linear
	Register set of the CPU	Register set of the CPU
	— General purpose:	— General purpose:
	Sixteen 32-bit registers	Sixteen 32-bit registers
	 Control: Eight 32-bit registers 	— Control: Ten 32-bit registers
	 Accumulator: One 64-bit register 	— Accumulator: Two 72-bit
		registers
	Basic instructions: 73	Basic instructions: 75, variable-length
		instruction format
		 Floating point instructions: 11
	DSP instructions: 9	DSP instructions: 23
	Addressing modes: 10	Addressing modes: 11
	Data arrangement	Data arrangement
	— Instructions: Little endian	— Instructions: Little endian
	Data: Selectable between little	 Data: Selectable between little
	endian or big endian	endian or big endian
	On-chip 32-bit multiplier:	On-chip 32-bit multiplier:
	$32 \times 32 \rightarrow 64$ bits	$32 \times 32 \rightarrow 64$ bits
	 On-chip divider: 32 / 32 → 32 bits 	 On-chip divider: 32 / 32 → 32 bits
	Barrel shifter: 32 bits	Barrel shifter: 32 bits
FPU	<u> </u>	Single-precision floating-point (32 bite)
		bits)
		Data types and floating-point Avanting conform to JEEE 754
		exceptions conform to IEEE 754 standard

Table 2-2 Comparison of CPU Registers

Register	Bit	RX111	RX140
EXTB		_	Exception table register
FPSW		_	Floating-point status word
ACC (RX111) ACC0, ACC1 (RX140)	_	Accumulator	Accumulator 0, accumulator 1

2.2 Operating Mode

Table 2-3 lists the Difference in the Operating Mode.

Table 2-3 Difference in the Operating Mode

Item	RX111	RX140
Operating modes	- Single-chip mode	- Single-chip mode
	- Boot mode:	- Boot mode:
	- SCI interface mode	- SCI interface mode
	- FINE interface	- FINE interface
	- USB interface mode	

2.3 Address Space

Figure 2.1 is a comparative memory map of single-chip mode.

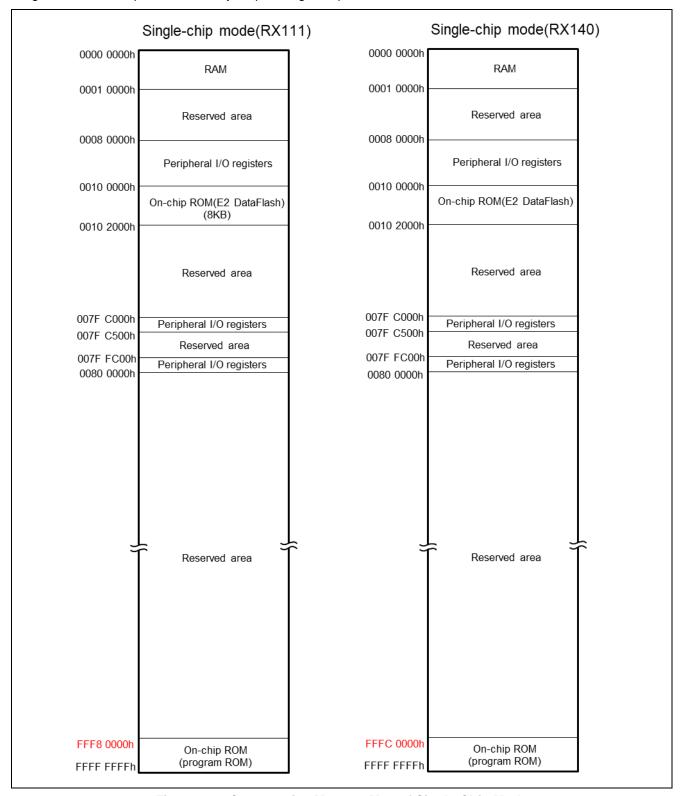


Figure 2.1 Comparative Memory Map of Single-Chip Mode

2.4 Resets

Table 2-4 is a comparative overview of resets, and Table 2-5 is a comparison of reset-related registers.

Table 2-4 Comparative Overview of Resets

Item	RX111	RX140
RES# pin reset	Voltage input to the RES# pin is	Voltage input to the RES# pin is
	driven low.	driven low.
Power-on reset	VCC rises	VCC rises
	(voltage detection: VPOR).	(voltage detection: VPOR).
Voltage monitoring 0 reset	_	VCC falls (voltage detection: Vdet0).
Voltage monitoring 1 reset	VCC falls (voltage detection: Vdet1).	VCC falls (voltage detection: Vdet1).
Voltage monitoring 2 reset	VCC falls (voltage detection: Vdet2).	VCC falls (voltage detection: Vdet2).
Independent watchdog	The independent watchdog timer	The independent watchdog timer
timer reset	underflows or a refresh error occurs.	underflows or a refresh error occurs.
Software reset	Register setting	Register setting

Table 2-5 Comparison of Reset-Related Registers

I	Register	Bit	RX111	RX140
I	RSTSR0	LVD0RF	_	Voltage monitor 0 reset detect flag

2.5 Option-Setting Memory

Table 2-6 is a comparison of option-setting memory registers.

Table 2-6 Comparison of Option-Setting Memory Registers

Register	Bit	RX111	RX140 (OFSM)
OFS1	FASTSTUP	Power-on fast startup time bit (b0)	Power-on fast startup time bit (b3)
	VDSEL[1:0]	_	Voltage detection 0 level select bits
	LVDAS	_	Voltage detection 0 circuit start bit
	STUPLVD1REN	Startup voltage monitoring 1 reset enable bits	
	STUPLVD1LVL [3:0]	Startup voltage monitoring 1 reset detection level select bits	
	HOCOFQ[1:0]	_	HOCO frequency selection bits

2.6 Voltage Detection Circuit

Table 2-7 is a comparative overview of the voltage detection circuits, and Table 2-8 is a comparison of voltage detection circuit registers.

Table 2-7 Comparative Overview of Voltage Detection Circuits

		RX111 (LVDAa)		RX140 (LVDAb)		
Item		Voltage Monitoring 1	Voltage Monitoring 2	Voltage Monitoring 0	Voltage Monitoring 1	Voltage Monitoring 2
VCC monitoring	Monitored voltage	Vdet1	Vdet2	Vdet0	Vdet1	Vdet2
	Detection target	When voltage rises above or drops past Vdet1	When voltage rises above or drops past Vdet2 Switching between VCC and the voltage input on the CMPA2 pin can be accomplished using the LVCMPCR.EXV CCINP2 bit.	When voltage drops below Vdet0	When voltage rises above or drops past Vdet1	When voltage rises above or drops past Vdet2 Switching between VCC and the voltage input on the CMPA2 pin can be accomplished using the LVCMPCR.EXV CCINP2 bit.
	Detection voltage	Selectable from ten levels using LVDLVLR.LVD1 LVL[3:0] bits	Selectable from four levels using LVDLVLR.LVD2 LVL[1:0] bits	Selectable from four levels using the OFS1 register	Selectable from 14 levels using LVDLVLR.LVD1 LVL[3:0] bits	Selectable from four levels using LVDLVLR.LVD2 LVL[1:0] bits
	Monitoring flags	LVD1SR.LVD1M ON flag: Monitors whether voltage is higher or lower than Vdet1	LVD2SR.LVD2M ON flag: Monitors whether voltage is higher or lower than Vdet2	_	LVD1SR.LVD1M ON flag: Monitors whether voltage is higher or lower than Vdet1	LVD2SR.LVD2M ON flag: Monitors whether voltage is higher or lower than Vdet2
		LVD1SR.LVD1D ET flag: Vdet1 passage detection	LVD2SR.LVD2D ET flag: Vdet2 passage detection	_	LVD1SR.LVD1D ET flag: Vdet1 passage detection	LVD2SR.LVD2D ET flag: Vdet2 passage detection
Voltage detection processing	Reset	Voltage monitoring 1 interrupt	Voltage monitoring 2 interrupt	Voltage monitoring 0 interrupt	Voltage monitoring 1 interrupt	Voltage monitoring 2 interrupt
		Reset when Vdet1 > VCC: CPU restart timing selectable between after specified time with VCC > Vdet1 or Vdet1 > VCC	Reset when Vdet2 > VCC or CMPA2 pin: CPU restart timing selectable among after specified time with VCC or CMPA2 pin > Vdet2 or after specified time with Vdet2 > VCC or CMPA2 pin	Reset when Vdet0 > VCC: CPU restart timing after specified time with VCC > Vdet0	Reset when Vdet1 > VCC: CPU restart timing selectable between after specified time with VCC > Vdet1 or Vdet1 > VCC	Reset when Vdet2 > VCC or CMPA2 pin: CPU restart timing selectable among after specified time with VCC or CMPA2 pin > Vdet2 or after specified time with Vdet2 > VCC or CMPA2 pin

	RX111 ((LVDAa)		RX140 (LVDAb)	
Item		Voltage Monitoring 1	Voltage Monitoring 2	Voltage Monitoring 0	Voltage Monitoring 1	Voltage Monitoring 2
Voltage detection processing	Interrupts	Voltage monitoring 1 interrupt Selectable between non- maskable or maskable interrupt Interrupt request issued when Vdet1 > VCC, VCC > Vdet1, or both	Voltage monitoring 2 interrupt Selectable between non- maskable or maskable interrupt Interrupt request issued when Vdet2 > VCC or CMPA2 pin, VCC or CMPA2 pin > Vdet2, or both		Voltage monitoring 1 interrupt Selectable between non- maskable or maskable interrupt Interrupt request issued when Vdet1 > VCC, VCC > Vdet1, or both	Voltage monitoring 2 interrupt Selectable between non- maskable or maskable interrupt Interrupt request issued when Vdet2 > VCC, VCC > Vdet2, or both
Event link function		Available: Event output at Vdet1 passage detection	_	_	Available: Event output at Vdet1 passage detection	_

Table 2-8 Comparison of Voltage Detection Circuit Registers

Register	Bit	RX111 (LVDAa)	RX140 (LVDAb)
LVDLVLR	LVD1LVL[3:0]	Voltage detection 1 level select bits	Voltage detection 1 level select bits
		(Standard voltage during drop in	(Standard voltage during drop in
		voltage)	voltage)
		b3 b0	b3 b0
			0 0 0 0: 4.29 V
			0 0 0 1: 4.16 V
			0 0 1 0: 4.03 V
			0 0 1 1: 3.86 V
		0 1 0 0: 3.10 V	0 1 0 0: 3.10 V
		0 1 0 1: 3.00 V	0 1 0 1: 3.00 V
		0 1 1 0: 2.90 V	0 1 1 0: 2.90 V
		0 1 1 1: 2.79 V	0 1 1 1: 2.80 V
		1 0 0 0: 2.68 V	1 0 0 0: 2.68 V
		1 0 0 1: 2.58 V	1 0 0 1: 2.59 V
		1 0 1 0: 2.48 V	1 0 1 0: 2.48 V
		1 0 1 1: 2.06 V	1 0 1 1: 2.20 V
		1 1 0 0: 1.96 V	1 1 0 0: 1.96 V
		1 1 0 1: 1.86 V	1 1 0 1: 1.86 V
		Settings other than the above are	Settings other than the above are
		prohibited.	prohibited.
	LVD2LVL[1:0]	Voltage detection 2 level select bits	Voltage detection 2 level select bits
		(Standard voltage during drop in	(Standard voltage during drop in
		voltage)	voltage)
		b5 b4	b5 b4
		0 0: 2.90 V	0 0: 4.32 V
		0 1: 2.60 V	0 1: 4.17 V
		1 0: 2.00 V	1 0: 4.03 V
		1 1: 1.80 V*1	1 1: 3.84 V

Note: 1. When the value of the LVCMPCR.EXVCCINP2 bit is 0 (power supply voltage (VCC)), the setting value of 11b is prohibited.

2.7 Clock Generation Circuit

Table 2-9 is a comparative overview of the clock generation circuits, and Table 2-10 is a comparison of clock generation circuit registers.

Table 2-9 Comparative Overview of Clock Generation Circuits

Item	RX111	RX140
Uses	 Generates the system clock (ICLK) to be supplied to the CPU, DTC, ROM, and RAM. Of the peripheral module clocks (PCLKB and PCLKD) supplied to the peripheral modules, PCLKD is the operating clock for the S12AD, and PCLKB is the operating clock for modules other than S12AD. Generates the FlashIF clock (FCLK) to be supplied to the FlashIF. Generates the CAC clock (CACCLK) to be supplied to the CAC. 	 Generates the system clock (ICLK) to be supplied to the CPU, DTC, ROM, and RAM. Of the peripheral module clocks (PCLKB and PCLKD) supplied to the peripheral modules, PCLKD is the operating clock for the S12AD, and PCLKB is the operating clock for modules other than S12AD. Generates the FlashIF clock (FCLK) to be supplied to the FlashIF. Generates the CAC clock (CACCLK) to be supplied to the CAC. Generates the CAN clock (CANMCLK) to be supplied to the
	 Generates the RTC-dedicated sub-clock (RTCSCLK) to be supplied to the RTC. Generates the IWDT-dedicated clock (IWDTCLK) to be supplied to the IWDT. 	 CANMCLK) to be supplied to the CAN. Generates the RTC-dedicated sub-clock (RTCSCLK) to be supplied to the RTC. Generates the IWDT-dedicated clock (IWDTCLK) to be supplied to the IWDT Generates the LPT clock (LPTCLK) to be supplied to the LPT.
Operating frequency	 Generates the USB clock (UCLK) to be supplied to the USB. ICLK: 32 MHz (max.) PCLKB: 32 MHz (max.) PCLKD: 32 MHz (max.) FCLK: — 1 MHz to 32 MHz (for programming and erasing the ROM and E2 DataFlash) — 32 MHz (max.) (for reading from the E2 DataFlash) UCLK: 48 MHz CACCLK: Same as clock from respective oscillators RTCSCLK: 32.768 kHz IWDTCLK: 15 kHz 	ICLK: 48 MHz (max.) PCLKB: 32 MHz (max.) PCLKD: 48 MHz (max.) FCLK: — 1 MHz to 48 MHz (for programming and erasing the ROM and E2 DataFlash) — 48 MHz (max.) (for reading from the E2 DataFlash) CACCLK: Same as clock from respective oscillators CANMCLK: 20 MHz (max.) RTCSCLK: 32.768 kHz IWDTCLK: 15 kHz LPTCLK: Same as clock from selected oscillator

Item	RX111	RX140
Main clock oscillator	 Resonator frequency: 1 MHz to 20 MHz (VCC ≥ 2.4 V), 1 MHz to 8 MHz (VCC < 2.4 V) 	Resonator frequency: 1 MHz to 20 MHz
	 External clock input frequency: 20 MHz (max.) 	 External clock input frequency: 20 MHz (max.)
	Connectable resonator or additional circuit: ceramic resonator, crystal	 Connectable resonator or additional circuit: ceramic resonator, crystal
	Connection pins: EXTAL, XTAL	Connection pins: EXTAL, XTAL
	Oscillation stop detection function: When a main clock oscillation stop is detected, the system clock source is switched to LOCO and MTU pin can be forcedly driven to high-impedance.	 Oscillation stop detection function: When a main clock oscillation stop is detected, the system clock source is switched to LOCO and MTU pin can be forcedly driven to high-impedance.
	Drive capacity switching function	Drive capacity switching function
Sub-clock oscillator	 Resonator frequency: 32.768 kHz Connectable resonator or additional circuit: crystal Connection pins: XCIN and XCOUT 	 Resonator frequency: 32.768 kHz Connectable resonator or additional circuit: crystal Connection pins: XCIN and XCOUT
		 Drive capacity switching function
PLL circuit	 Input clock source: Main clock Input pulse frequency division ratio: Selectable from 1, 2, and 4 Input frequency: 4 to 8 MHz Frequency multiplication ratio: Selectable from 6 and 8 VCO oscillation frequency: 32 to 48 MHz (VCC ≥ 2.4 V) 	 Input clock source: Main clock Input pulse frequency division ratio: Selectable from 1, 2, and 4 Input frequency: 4 MHz to 12 MHz Frequency multiplication ratio: Selectable from 4 to 12 (increments of 0.5) Oscillation frequency: 24 MHz to 48 MHz
High-speed on-chip oscillator (HOCO)	Oscillation frequency: 32 MHz	Oscillation frequency: 24 MHz, 32 MHz, 48 MHz
Low-speed on-chip oscillator (LOCO)	Oscillation frequency: 4 MHz	Oscillation frequency: 4 MHz
IWDT-dedicated on-chip oscillator	Oscillation frequency: 15 kHz	Oscillation frequency: 15 kHz

Table 2-10 Comparison of Clock Generation Circuit Registers

Register	Bit	RX111	RX140
SOSCCR	SOSTP	Sub-clock oscillator stop bit	Sub-clock oscillator stop bit
		Initial value after a recet differe	This bit is not initialized by reset sources other than a power-on reset.
OCCOVECD	DLOVE	Initial value after a reset differs.	DLL alock assillation atabilization
OSCOVFSR	PLOVF	_	PLL clock oscillation stabilization flag
			O: PLL is stopped or not stabilized. 1: Oscillation is stable and the clock can be used as the system clock.
MOSCWTCR	MSTS[4:0]	Main clock oscillator wait time bits	Main clock oscillator wait time bits
		b4 b0 0 0 0 0 0: Wait time = 2 cycles (0.5 μs) 0 0 0 0 1: Wait time = 1,024 cycles (256 μs) 0 0 0 1 0: Wait time = 2,048 cycles (512 μs) 0 0 0 1 1: Wait time = 4,096 cycles (1.024 ms) 0 0 1 0 0: Wait time = 8,192 cycles (2.048 ms) 0 0 1 0 1: Wait time = 16,384 cycles (4.096 ms) 0 0 1 1 0: Wait time = 32,768 cycles (8.192 ms) 0 0 1 1 1: Wait time = 65,536 cycles (16.384 ms)	b4 b0 0 0 0 0 0: Wait time = 0 cycles (0 μs) 0 0 0 0 1: Wait time = 1,024 cycles (256 μs) 0 0 0 1 0: Wait time = 2,048 cycles (512 μs) 0 0 0 1 1: Wait time = 4,096 cycles (1.024 ms) 0 0 1 0 0: Wait time = 8,192 cycles (2.048 ms) 0 0 1 0 1: Wait time = 16,384 cycles (4.096 ms) 0 0 1 1 0: Wait time = 32,768 cycles (8.192 ms) 0 0 1 1 1: Wait time = 65,536 cycles (16.384 ms) 0 1 0 0 0: Wait time = 131,072 cycles (32.768 ms) Settings other than the above are
		Settings other than the above are prohibited. Wait time when LOCO = 4.0 MHz (0.25 µs, typ.)	prohibited. Wait time when LOCO = 4.0 MHz (0.25 μ s, typ.)
LOFCR	_	_	Low-speed on-chip oscillator forced oscillation control register
HOCOWTCR	_	High-speed on-chip oscillator wait control register	—

Register	Bit	RX111	RX140
CKOCR	CKOSEL[2:0]	CLKOUT output source select bits	CLKOUT output source select bits
	(RX111)		
	CKOSEL[3:0] (RX140)	b10 b8	b11 b8
	(KX140)	0 0 0: LOCO clock	0 0 0 0: LOCO clock
		0 0 1: HOCO clock	0 0 0 1: HOCO clock
		0 1 0: Main clock oscillator 0 1 1: Sub-clock oscillator	0 0 1 0: Main clock oscillator 0 0 1 1: Sub-clock oscillator
		0 1 1. Sub-clock Oscillator	0 1 0 0: PLL
		Settings other than the above are	1 0 0 0: CTSU internal clock
		prohibited.	Settings other than the above are
		•	prohibited.
	CKODIV[2:0]	CLKOUT output division ratio	CLKOUT output division ratio
		select bits	select bits
		b14 b12	b14 b12
		0 0 0: No division	0 0 0: No division
		0 0 1: ×1/2	0 0 1: ×1/2
		0 1 0: ×1/4	0 1 0: ×1/4
		0 1 1: ×1/8	0 1 1: ×1/8
		1 0 0: ×1/16	1 0 0: ×1/16
		Settings other than the above are	1 0 1: ×1/32
		prohibited.	1 1 0: ×1/64
MOFCR	MODRV21	Main clock oscillator drive	1 1 1: ×1/128 Main clock oscillator drive
WOFCK	WODKV21	capability switch bit	capability switch bit
		VCC ≥ 2.4 V	
		0: 1 MHz to 10 MHz	0: 1 MHz to less than 10 MHz
		1: 10 MHz to 20 MHz	1: 10 MHz to 20 MHz
		1. 10 1/11/2 to 20 1/11/2	1. 10 Wil 12 to 20 Wil 12
		VCC < 2.4 V	
		0: 1 MHz to 8 MHz	
		1: Setting prohibited	
LOCOTRR2		_	Low-speed on-chip oscillator
			trimming register 2
ILOCOTRR		_	IWDT-dedicated on-chip oscillator
HOCOTRRn			trimming register High-speed on-chip oscillator
HOCOTRRII		_	trimming register n (n = 0)
SOMCR	_	_	Sub-clock oscillator mode control
			register

Register	Bit	RX111	RX140
PLLCR	STC[5:0]	Frequency Multiplication	Frequency Multiplication
		Factor Select	Factor Select
		b13 b8	B13 b8
			0 0 1 0 0 0 : x4.5
			001000: x4.3
			0 0 1 0 1 0 : x5.5
		0 0 1 0 1 1 : x6	0 0 1 0 1 1 : x6
			0 0 1 1 0 0 : x6.5
			0 0 1 1 0 1 : x7
			0 0 1 1 1 0 : x7.5
		0 0 1 1 1 1 : x8	0 0 1 1 1 1 : x8
			0 1 0 0 0 0 : x8.5
			0 1 0 0 0 1 : x9
			0 1 0 0 1 0 : x9.5
			0 1 0 0 1 1 : x10
			0 1 0 1 0 0 : x10.5
			0 1 0 1 0 1 : x11
			0 1 0 1 1 0 : x11.5
			0 1 0 1 1 1 : x12
		Settings other than above are	Settings other than above are
		prohibited.	prohibited.

2.8 Low Power Consumption

Table 2-11 is a comparative overview of the low power consumption functions, Table 2-12 is a comparison of procedures for entering and exiting low power consumption modes and operating states in each mode, and Table 2-13 is a comparison of low power consumption registers.

Table 2-11 Comparative Overview of Low Power Consumption Functions

Item	RX111	RX140
Reducing power consumption by switching clock signals	The frequency division ratio can be set independently for the system clock (ICLK), peripheral module clock (PCLKB), S12AD clock (PCLKD), and FlashIF clock (FCLK).	The frequency division ratio can be set independently for the system clock (ICLK), peripheral module clock (PCLKB), S12AD clock (PCLKD), and FlashIF clock (FCLK).
Module stop function	Each peripheral module can be stopped independently by the module stop control register.	Each peripheral module can be stopped independently by the module stop control register.
Function for transition to low power consumption mode	Transition to a low power consumption mode in which the CPU, peripheral modules, or oscillators are stopped is enabled.	Transition to a low power consumption mode in which the CPU, peripheral modules, or oscillators are stopped is enabled.
Low power consumption modes	Sleep modeDeep sleep modeSoftware standby mode	 Sleep mode Deep sleep mode Software standby mode Snooze mode
Function for lower operating power consumption	 Power consumption can be reduced in normal operation, sleep mode, and deep sleep mode by selecting an appropriate operating power control mode according to the operating frequency and operating voltage. Three operating power control modes are available High-speed operating mode Middle-speed operating mode 	 Power consumption can be reduced in normal operation, sleep mode, deep sleep mode, and snooze mode by selecting an appropriate operating power control mode according to the operating frequency and operating voltage. Four operating power control modes are available High-speed operating mode Middle-speed operating mode Middle-speed operating mode
	 Low-speed operating mode 	2 — Low-speed operating mode

Table 2-12 Comparison of Procedures for Entering and Exiting Low Power Consumption Modes and Operating States in Each Mode

	Entering and Exiting Low Power Consumption Modes and		
Mode	Operating States	RX111	RX140
Sleep mode	Transition method	Control register	Control register
		+ instruction	+ instruction
	Method of cancellation other than reset	Interrupt	Interrupt
	State after cancellation	Program execution	Program execution
		state (interrupt	state (interrupt
		processing)	processing)
	Main clock oscillator	Operation possible	Operation possible
	Sub-clock oscillator	Operation possible	Operation possible
	High-speed on-chip oscillator	Operation possible	Operation possible
	Low-speed on-chip oscillator	Operation possible	Operation possible
	IWDT-dedicated on-chip oscillator	Operation possible	Operation possible
	PLL	Operation possible	Operation possible
	CPU	Stopped (retained)	Stopped (retained)
	RAM0	Operation possible	Operation possible
	(0000 0000h to 0000 3FFFh: RX111,	(retained)	(retained)
	0000 0000h to 0000 FFFFh: RX140)		
	DTC	Operation possible	Operation possible
	Flash memory	Operation	Operation
	Independent watchdog timer (IWDT)	Operation possible	Operation possible
	Realtime clock (RTC)	Operation possible	Operation possible
	Low-power timer (LPT)	_	Operation possible
	Voltage detection circuit (LVD)	Operation possible	Operation possible
	Power-on reset circuit	Operation	Operation
	Peripheral modules	Operation possible	Operation possible
	I/O ports	Operation	Operation
	RTCOUT output	Operation possible	Operation possible
	CLKOUT output	Operation possible	Operation possible
	Comparator B	_	Operation possible
Deep sleep mode	Transition method	Control register + instruction	Control register + instruction
	Method of cancellation other than reset	Interrupt	Interrupt
	State after cancellation	Program execution	Program execution
		state (interrupt	state (interrupt
		processing)	processing)
	Main clock oscillator	Operation possible	Operation possible
	Sub-clock oscillator	Operation possible	Operation possible
	High-speed on-chip oscillator	Operation possible	Operation possible
	Low-speed on-chip oscillator	Operation possible	Operation possible
	IWDT-dedicated on-chip oscillator	Operation possible	Operation possible
	PLL	Operation possible	Operation possible
	CPU	Stopped (retained)	Stopped (retained)
	RAM0	Stopped (retained)	Stopped (retained)
	(0000 0000h to 0000 3FFFh: RX111,	,	
	0000 0000h to 0000 FFFFh: RX140)		
	DTC	Stopped (retained)	Stopped (retained)
	Flash memory	Stopped (retained)	Stopped (retained)
	Independent watchdog timer (IWDT)	Operation possible	Operation possible
	Realtime clock (RTC)	Operation possible	Operation possible

Mode	Entering and Exiting Low Power Consumption Modes and Operating States	RX111	RX140
Deep sleep	Low-power timer (LPT)	_	Operation possible
mode	Voltage detection circuit (LVD)	Operation possible	Operation possible
	Power-on reset circuit	Operation	Operation
	Peripheral modules	Operation possible	Operation possible
	I/O ports	Operation	Operation
	RTCOUT output	Operation possible	Operation possible
	CLKOUT output	Operation possible	Operation possible
	Comparator B	Operation possible	Operation possible
Software	Transition method	Control register	Control register
standby mode		+ instruction	+ instruction
	Method of cancellation other than reset	Interrupt	Interrupt
	State after cancellation	Program execution state (interrupt processing)	Program execution state (interrupt processing)
	Main clock oscillator	Stopped	Stopped
	Sub-clock oscillator	Operation possible	Operation possible
	High-speed on-chip oscillator	Stopped	Operation possible
	Low-speed on-chip oscillator	Stopped	Operation possible
	IWDT-dedicated on-chip oscillator	Operation possible	Operation possible
	PLL	Stopped	Stopped
	CPU	Stopped (retained)	Stopped (retained)
	RAM0 (0000 0000h to 0000 3FFFh: RX111, 0000 0000h to 0000 FFFFh: RX140)	Stopped (retained)	Stopped (retained)
	DTC	Stopped (retained)	Stopped (retained)
	Flash memory	Stopped (retained)	Stopped (retained)
	Independent watchdog timer (IWDT)	Operation possible	Operation possible
	Realtime clock (RTC)	Operation possible	Operation possible
	Low-power timer (LPT)		Operation possible
	Voltage detection circuit (LVD)	Operation possible	Operation possible
	Power-on reset circuit	Operation	Operation
	Peripheral modules	Stopped (retained)	Stopped (retained)
	I/O ports	Retained	Retained
	RTCOUT output	Operation possible	Operation possible
	CLKOUT output	Operation possible	Operation possible
	Comparator B	_	Operation possible
Snooze mode	Transition method	_	Occurrence of snooze request condition while in software standby mode
	Method of cancellation other than reset	_	Interrupt or occurrence of snooze end condition
	State after cancellation		Program execution state (interrupt processing) or software standby mode
	Main clock oscillator		Operation possible

	Entering and Exiting Low Power Consumption Modes and		
Mode	Operating States	RX111	RX140
Snooze mode	Sub-clock oscillator	_	Operation possible
	High-speed on-chip oscillator	_	Operation possible
	Low-speed on-chip oscillator	_	Operation possible
	IWDT-dedicated on-chip oscillator	_	Operation possible
	PLL	_	Operation possible
	CPU	_	Stopped (retained)
	RAM0	_	Operation possible
	(0000 0000h to 0000 3FFFh: RX111, 0000 0000h to 0000 FFFFh: RX140)		(retained)
	DTC	_	Operation possible
	Flash memory	_	Stopped (retained)
	Independent watchdog timer (IWDT)	_	Operation possible
	Realtime clock (RTC)	_	Operation possible
	Low-power timer (LPT)	_	Operation possible
	Voltage detection circuit (LVD)	_	Operation possible
	Power-on reset circuit	_	Operation
	Peripheral modules	_	Operation possible
	I/O ports		Operation
	RTCOUT output		Operation possible
	CLKOUT output	_	Operation possible
	Comparator B	_	Operation possible

Note: "Operation possible" means that whether the state is operating or stopped is controlled by the control register setting.

[&]quot;Stopped (retained)" means that internal register values are retained and internal operations are suspended.

[&]quot;Stopped (undefined)" means that internal register values are undefined and power is not supplied to the internal circuit.

Table 2-13 Comparison of Low Power Consumption Registers

Register	Bit	RX111	RX140
MSTPCRA	MSTPA4	_	8-bit timer 3/2 (unit 1) module stop bit
	MSTPA5	_	8-bit timer 1/0 (unit 0) module stop bit
	MSTPA19	D/A converter module stop bit	D/A converter module stop bit
MSTPCRB	MSTPB0	_	CAN module module stop bit
	MSTPB9	ELC module stop bit	ELC module stop bit
	MSTPB10	_	Comparator B module stop bit
	MSTPB10		
	MSTPB19	USB0 module stop bit*1	
	MSTPB25	_	Serial communication interface 6 module stop bit
MSTPCRC	_	Module stop control register C	Module stop control register C
		Initial value after a reset differs.	
	MSTPC26	_	Serial communication interface 9 module stop bit
	MSTPC27	_	Serial communication interface 8 module stop bit
MSTPCRD	_	_	Module stop control register D
OPCCR	OPCM[2:0]	Operating power control mode select bits	Operating power control mode select bits
		b2 b0	b2 b0
		0 0 0: High-speed operating mode	0 0 0: High-speed operating mode
		0 1 0: Middle-speed operating mode	0 1 0: Middle-speed operating mode
			1 0 0: Middle-speed operating mode 2
		Settings other than the above are prohibited.	Settings other than the above are prohibited.
SNZCR	_	_	Snooze control register
SNZCR2	_	_	Snooze control register 2

Note 1. This bit should be rewritten while the oscillation of the clock to be controlled by this bit is stable. When entering software standby mode after rewriting this bit, wait for two cycles of the UCLK after rewriting, and execute a WAIT instruction.

2.9 Register Write Protection Function

Table 2-14 is a comparative overview of the register write protection functions, and Table 2-15 is a comparison of register write protection function registers.

Table 2-14 Comparative Overview of Register Write Protection Functions

Item	RX111	RX140	
PRC0 bit	Registers related to the clock generation circuit: SCKCR, SCKCR3, PLLCR, PLLCR2, MOSCCR, SOSCCR, LOCOCR, ILOCOCR, HOCOCR, OSTDCR, OSTDSR, CKOCR	Registers related to the clock generation circuit: SCKCR, SCKCR3, PLLCR, PLLCR2, MOSCCR, SOSCCR, LOCOCR, ILOCOCR, HOCOCR, LOFCR, OSTDCR, OSTDSR, CKOCR, LOCOTRR2, ILOCOTRR, HOCOTRR0, SOMCR	
PRC1 bit	 Register related to the operating modes: SYSCR1 Registers related to the low power consumption functions: SBYCR, MSTPCRA, MSTPCRB, MSTPCRC, OPCCR, RSTCKCR, SOPCCR Registers related to the clock generation circuit: MOFCR, MOSCWTCR Software reset register: SWRR 	Register related to the operating modes: SYSCR1 Registers related to the low power consumption functions: SBYCR, MSTPCRA, MSTPCRB, MSTPCRC, MSTPCRD, OPCCR, RSTCKCR, SOPCCR, SNZCR, SNZCR2 Registers related to the clock generation circuit: MOFCR, MOSCWTCR Software reset register: SWRR	
PRC2 bit	Registers related to the clock generation circuit: HOCOWTCR	Registers related to the low power timer: LPTCR1, LPTCR2, LPTCR3, LPTPRD, LPCMR0, LPCMR1, LPWUCR	
PRC3 bit	Registers related to LVD: LVCMPCR, LVDLVLR, LVD1CR0, LVD1CR1, LVD1SR, LVD2CR0, LVD2CR1, LVD2SR	Registers related to LVD: LVCMPCR, LVDLVLR, LVD1CR0, LVD1CR1, LVD1SR, LVD2CR0, LVD2CR1 LVD2SR	

Table 2-15 Comparison of Register Write Protection Function Registers

Register	Bit	RX111	RX140
PRCR	PRC2	Enables writing to the registers related to the clock generation circuit.	Enables writing to the registers related to the low-power timer.

2.10 Exception Handling

Table 2-16 is a comparative overview of exception handling, Table 2-17 is a comparative listing of vectors, and Table 2-18 is a comparative listing of instructions for returning from exception handling routines.

Table 2-16 Comparative Overview of Exception Handling

Item	RX111	RX140
Exception events	Undefined instruction exception	Undefined instruction exception
	 Privileged instruction exception 	 Privileged instruction exception
		Access exception
		 Floating-point exception
	Reset	Reset
	 Non-maskable interrupt 	Non-maskable interrupt
	Interrupt	Interrupt
	 Unconditional trap 	Unconditional trap

Table 2-17 Comparative Listing of Vectors

Item		RX111	RX140
Undefined	instruction exception	Fixed vector table	Exception vector table (EXTB)
Privileged i	instruction exception	Fixed vector table	Exception vector table (EXTB)
Access exc	ception	_	Exception vector table (EXTB)
Floating-po	oint exception	_	Exception vector table (EXTB)
Reset		Fixed vector table	Exception vector table (EXTB)
Non-maska	able interrupt	Fixed vector table	Exception vector table (EXTB)
Interrupt	Fast interrupt	FINTV	FINTV
Other than fast interrupt		Relocatable vector table (INTB)	Relocatable vector table (INTB)
Unconditio	nal trap	Relocatable vector table (INTB)	Relocatable vector table (INTB)

Table 2-18 Comparative Listing of Instructions for Returning from Exception Handling Routines

Item		RX111	RX140
Undefined i	instruction exception	RTE	RTE
Privileged i	nstruction exception	RTE	RTE
Access exc	eption	_	RTE
Floating-po	int exception	_	RTE
Reset		Return not possible	Return not possible
Non-maska	ıble interrupt	Return not possible	Prohibited
Interrupt	Fast interrupt	RTFI	RTFI
Other than fast interrupt		RTE	RTE
Uncondition	nal trap	RTE	RTE

2.11 Interrupt Controller

Table 2-19 is a comparative overview of the interrupt controllers, and Table 2-20 is a comparison of interrupt controller registers.

Table 2-19 Comparative Overview of Interrupt Controllers

Item		RX111 (ICUb)	RX140 (ICUb)	
Interrupts	Peripheral function interrupts	 Interrupts from peripheral modules Interrupt detection: Edge detection/level detection The detection method is fixed for each connected peripheral module source. 	 Interrupts from peripheral modules Interrupt detection: Edge detection/level detection The detection method is fixed for each connected peripheral module source. 	
	External pin interrupts	 Interrupts from pins IRQ0 to IRQ7 Number of sources: 8 Interrupt detection: Ability to set as source detection of low level, falling edge, rising edge, or rising and falling edges Digital filter function: Supported 	 Interrupts from pins IRQ0 to IRQ7 Number of sources: 8 Interrupt detection: Ability to set as source detection of low level, falling edge, rising edge, or rising and falling edges Digital filter function: Supported 	
	Software interrupts	 Interrupt generated by writing to a register Number of sources: 1 	Interrupt generated by writing to a registerNumber of sources: 1	
	Event link interrupts	The ELSR18I interrupt is generated by an ELC event	An ELSR8I or ELSR18I interrupt can be generated by an ELC event.	
	Interrupt priority	Specified by registers.	Specified by registers.	
	Fast interrupt function	Faster interrupt handling by the CPU can be specified for a single interrupt source only.	Faster interrupt handling by the CPU can be specified for a single interrupt source only.	
	DTC control	The DTC can be activated by an interrupt source.	The DTC can be activated by an interrupt source.	
Non- maskable interrupts	NMI pin interrupt Oscillation	 Interrupt from the NMI pin Interrupt detection: Falling edge or rising edge Digital filter function: Supported Interrupt on detection of oscillation 	 Interrupt from the NMI pin Interrupt detection: Falling edge or rising edge Digital filter function: Supported Interrupt on detection of oscillation 	
	stop detection interrupt	having stopped	having stopped	
	IWDT underflow/ refresh error interrupt	Interrupt on an underflow of the down counter or occurrence of a refresh error	Interrupt on an underflow of the down counter or occurrence of a refresh error	
	Voltage monitoring 1 interrupt	Voltage monitoring interrupt of voltage monitoring circuit 1 (LVD1)	Voltage monitoring interrupt of voltage monitoring circuit 1 (LVD1)	
	Voltage monitoring 2 interrupt	Voltage monitoring interrupt of voltage monitoring circuit 2 (LVD2)	Voltage monitoring interrupt of voltage monitoring circuit 2 (LVD2)	

Item	RX111 (ICUb)	RX140 (ICUb)
Return from low power consumption state	 Sleep mode and deep sleep mode: Return is initiated by a non-maskable interrupt or any other interrupt source. Software standby mode: Return is initiated by a non-maskable interrupt, interrupt IRQ0 to IRQ7, or an RTC alarm or peripheral interrupt. 	 Sleep mode and deep sleep mode: Return is initiated by a non-maskable interrupt or any other interrupt source. Software standby mode: Return is initiated by a non-maskable interrupt, interrupt IRQ0 to IRQ7, or an RTC alarm or peripheral interrupt. Snooze mode: Return is initiated by a non-maskable interrupt, interrupt IRQ0 to IRQ7, or an RTC alarm or peripheral interrupt.

Table 2-20 Comparison of Interrupt Controller Registers

Register	Bit	RX111 (ICUb)	RX140 (ICUb)
IRn*1	_	Interrupt request register n (n = 016 to 249)	Interrupt request register n (n = 016 to 255)
IPRn*1	_	Interrupt source priority register n (n = 000 to 249)	Interrupt source priority register n (n = 000 to 255)
DTCERn*1		DTC activation enable register n (n = 027 to 248)	DTC transfer request enable register n (n = 027 to 255)

Note: 1. On the RX111 Group n = 250 to 255 correspond to a reserved area.

2.12 Buses

Table 2-21 is a comparative overview of the buses.

Table 2-21 Comparative Overview of Buses

Bus Type		RX111	RX140
CPU buses	Instruction bus	Connected to the CPU (for instructions) Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK)	Connected to the CPU (for instructions) Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK)
	Operand bus	 Connected to the CPU (for operands) Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK) 	 Connected to the CPU (for operands) Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK)
Memory buses	Memory bus 1	Connected to RAM	Connected to RAM
	Memory bus 2	Connected to ROM	Connected to ROM
Internal main buses	Internal main bus 1	 Connected to the CPU Operates in synchronization with the system clock (ICLK) 	 Connected to the CPU Operates in synchronization with the system clock (ICLK)
	Internal main bus 2	 Connected to the DTC Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK) 	 Connected to the DTC Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK)
Internal peripheral buses	Internal peripheral bus 1	 Connected to peripheral modules (DTC, interrupt controller, and bus error monitoring section) Operates in synchronization with the system clock (ICLK) 	 Connected to peripheral modules (DTC, interrupt controller, and bus error monitoring section) Operates in synchronization with the system clock (ICLK)
	Internal peripheral bus 2	 Connected to peripheral modules Operates in synchronization with the peripheral module clock (PCLKB) 	 Connected to peripheral modules Operates in synchronization with the peripheral module clock (PCLKB, PCLKD)
	Internal peripheral bus 3	 Connected to peripheral modules (USB) Operates in synchronization with the peripheral module clock (PCLKB) 	 Connected to peripheral modules (CTSU, RSCAN0) Operates in synchronization with the peripheral module clock (PCLKB)

Bus Type		RX111	RX140
Internal peripheral buses	Internal peripheral bus 6	 Connected to ROM (P/E) and E2 DataFlash Operates in synchronization with the FlashIF clock (FCLK) 	 Connected to ROM (P/E) and E2 DataFlash Operates in synchronization with the FlashIF clock (FCLK)

2.13 Data Transfer Controller

Table 2-22 is a comparative overview of the data transfer controllers, and Table 2-23 is a comparison of data transfer controller registers.

Table 2-22 Comparative Overview of Data Transfer Controllers

Item	RX111 (DTCa)	RX140 (DTCb)
Number of	Equal to number of all interrupt sources	Equal to number of all interrupt sources
transfer channels	that can start a DTC transfer.	that can start a DTC transfer.
Transfer modes	 Normal transfer mode A single activation leads to a single data transfer. Repeat transfer mode A single activation leads to a single data transfer. The transfer address returns to the transfer start address when the number of data transfers equals the repeat size. The maximum number of repeat transfers is 256, and the maximum data transfer size is 256 × 32 bits, or 1,024 bytes. Block transfer mode 	 Normal transfer mode A single activation leads to a single data transfer. Repeat transfer mode A single activation leads to a single data transfer. The transfer address returns to the transfer start address when the number of data transfers equals the repeat size. The maximum number of repeat transfers is 256, and the maximum data transfer size is 256 × 32 bits, or 1,024 bytes. Block transfer mode
	 A single activation leads to the transfer of a single block of data. The maximum block size is 256 x 32 bits = 1,024 bytes. 	 A single activation leads to the transfer of a single block of data. The maximum block size is 256 × 32 bits = 1,024 bytes.
Chain transfer function	 Multiple data transfers can be executed in response to a single transfer request (chain transfer). Either "performed only when the transfer counter reaches 0" or "performed every time" can be selected for chain transfers. 	 Multiple data transfer types can be executed sequentially in response to a single transfer request. Either "performed only when the transfer counter reaches 0" or "every time" can be selected.

Item	RX111 (DTCa)	RX140 (DTCb)
Sequence transfer		A complex series of transfers can be registered as a sequence. Any sequence can be selected by the transfer data and executed. Only one sequence transfer trigger source can be selected at a time. Up to 256 sequences can correspond to a single trigger source. The data that is initially transferred in response to a transfer request determines the sequence. The entire sequence can be executed on a single request, or the sequence can be suspended in the middle and resumed on the next transfer request (sequence
Transfer space	16 MB in short-address mode (within 0000 0000h to 007F FFFFh or FF80 0000h to FFFF FFFFh, excluding reserved areas) 4 GB in full-address mode (within 0000 0000h to FFFF FFFFh, excluding reserved areas)	division). 16 MB in short-address mode (within 0000 0000h to 007F FFFFh or FF80 0000h to FFFF FFFFh, excluding reserved areas) 4 GB in full-address mode (within 0000 0000h to FFFF FFFFh, excluding reserved areas)
Data transfer units	 Single data unit: 1 byte (8 bits), 1 word (16 bits), or 1 longword (32 bits) Single block size: 1 to 256 data units 	 Single data unit: byte (8 bits), 1 word (16 bits), or longword (32 bits) Single block size: 1 to 256 data units
CPU interrupt requests	 An interrupt request to the CPU can be generated by a DTC activation interrupt. An interrupt request to the CPU can be generated after a single data transfer. An interrupt request to the CPU can be generated after transfer of the specified number of data units. 	 An interrupt request to the CPU can be generated by a DTC activation interrupt. An interrupt request to the CPU can be generated after a single data transfer. An interrupt request to the CPU can be generated after transfer of the specified number of data units.
Event link function	An event link request is generated after one data transfer (for block, after one block transfer).	An event link request is generated after one data transfer (for block transfers, after one block).
Read skip	Transfer information read skipping can be specified.	Reading of the transfer information can be skipped when the same transfer is repeated.
Write-back skip	Write-back can be skipped when the address of the transfer source or destination is fixed.	Write-back of transferred data that is not updated can be skipped when the address of the transfer source or destination is fixed.

Item	RX111 (DTCa)	RX140 (DTCb)
Write-back disable	_	Ability to disable write-back of transfer information
Displacement addition	_	Ability to add displacement to the transfer source address (selectable by each transfer information)
Low power consumption function	Ability to specify module stop state	Ability to transition to module stop state

Table 2-23 Comparison of Data Transfer Controller Registers

Register	Bit	RX111 (DTCa)	RX140 (DTCb)
MRA	WBDIS	_	Write-back disable bit*1
MRB	SQEND	_	Sequence transfer end bit
	INDX	_	Index table reference bit
MRC	_	_	DTC mode register C
DTCIBR	_	_	DTC index table base register
DTCOR	_	_	DTC operation register
DTCSQE	_	_	DTC sequence transfer enable
			register
DTCDISP	_	_	DTC address displacement register

Note: 1. Transfer information is usually allocated to a RAM area, but it can be allocated to a ROM area by setting the MRA.WBDIS bit to 1 (no write-back).

2.14 Event Link Controller (ELC)

Table 2-24 is a comparative overview of the event link controller, and Table 2-25 is a comparison of event link controller registers.

Table 2-24 Comparative Overview of Event Link Controller

Item	RX111	RX140
Event link function	 36 types of event signals can be directly connected to modules. The operation of timer modules can be selected when an event is input to the timer module. Event link operation is possible for port B. Single port*1: An event link can be set for a single bit specified in a port. Port group*1: An event link can be set for a group of single bits specified within eight I/O ports. 	 48 types of event signals can be directly interconnected to modules. Operation for timer modules when inputting an event signal can be selected. Event linkage operation is possible for port B. Single port*1: Event linkage operation can be set in a single specified port. Port group*1: Event linkage operation can be set by grouping multiple specified ports among total of eight ports.
Low power consumption function	Module stop state can be set.	Module stop state can be set.

Note 1. The single port and port group specified as the input generate an event according to the change in the connected signal value.

In products with 64-pin packages, when ports PC0 and PC1 are selected in port switching register A (PSRA), ports PB6 and PB7 of the ELC cannot be used as input and output events. In products with 48-pin packages, when ports PC0 to PC3 are selected in port switching register B

In products with 48-pin packages, when ports PC0 to PC3 are selected in port switching register E (PSRB), ports PB0, PB1, PB3, and PB5 of the ELC cannot be used as input and output events.

Table 2-25 Comparison of Event Link Controller Registers

Register	Bit	RX111	RX140
ELSRn	_	Event Link Setting Register n	Event Link Setting Register n
		(n = 1 to 4, 7, 15, 16, 18, 20, 22,	(n = 1 to 4, 7, 8, 10, 12, 14 to 16,
		24, 25)	18, 20, 22, 24, 25)
ELOPC	LPTMD[1:0]	_	LPT Operation Select
ELOPD	TMR0MD[1:0]	_	TMR0 Operation Select
	TMR2MD[1:0]	_	TMR2 Operation Select

2.15 I/O Ports

Table 2-26 and Table 2-27 are comparative overviews of the I/O ports, Table 2-28 is a comparison of I/O port functions, and Table 2-29 is a comparison of I/O port registers.

Table 2-26 Comparative Overview of I/O Ports (64-Pin)

Port Symbol	RX111 (64-Pin)	RX140 (64-Pin)
PORT0	P03, P05	P03, P05
PORT1	P14 to P17	P14 to P17
PORT2	P26, P27	P26, P27
PORT3	P30 to P32, P35	P30 to P32, P35 to P37
PORT4	P40 to P44, P46	P40 to P47
PORT5	P54, P55	P54, P55
PORTA	PA0, PA1, PA3, PA4, PA6	PA0, PA1, PA3, PA4, PA6
PORTB	PB0, PB1, PB3, PB5 to PB7	PB0, PB1, PB3, PB5 to PB7
PORTC	PC2 to PC7	PC0 to PC7
PORTE	PE0 to PE7	PE0 to PE5
PORTG	_	PG7
PORTH	_	PH0 to PH3, PH6*1, PH7*1
PORTJ	PJ6, PJ7	PJ6, PJ7

Note: 1. A product with a ROM capacity of 64 KB is not equipped with this pin.

Table 2-27 Comparative Overview of I/O Ports (48-Pin)

Port Symbol	RX111 (48-Pin) RX140 (48-Pin)	
PORT1	P14 to P17 P14 to P17	
PORT2	P26, P27	P26, P27
PORT3	P35	P30, P31, P35 to P37
PORT4	P40 to P42, P46	P40 to P42, P45 to P47
PORTA	PA1, PA3, PA4, PA6	PA1, PA3, PA4, PA6
PORTB	PB0, PB1, PB3, PB5	PB0, PB1, PB3, PB5
PORTC	PC4 to PC7	PC0 to PC7
PORTE	PE0 to PE4, PE7	PE1 to PE4
PORTG	_	PG7
PORTH	_	PH0 to PH3
PORTJ	PJ6, PJ7	PJ6, PJ7

Table 2-28 Comparison of I/O Port Functions

Item	Port Symbol	RX111	RX140
Input pull-up function	PORT0	P03, P05	P03 to P07
	PORT1	P14, P15, P16, P17	P12 to P17
	PORT2	P26, P27	P20, P21, P26, P27
	PORT3	P30 to P32	P30 to P32, P34, P36, P37
	PORT4	_	P40 to P47
	PORT5	P54, P55	P54, P55
	PORTA	PA0, PA1, PA3, PA4, PA6	PA0 to PA6
	PORTB	PB0, PB1, PB3, PB5 to PB7	PB0 to PB7
	PORTC	PC0 to PC7	PC2 to PC7
	PORTD	_	PD0 to PD2
	PORTE	PE0 to PE7	PE0 to PE3, PE4, PE5
	PORTG	_	PG7
	PORTH	_	PH0 to PH3
	PORTJ	_	PJ1, PJ6, PJ7
Open drain output	PORT1	P14 to P17	P12 to P17
function	PORT2	P26, P27	P20, P21, P26, P27
	PORT3	P30 to P32	P30 to P32, P34, P36, P37
	PORTA	PA0, PA1, PA3, PA4, PA6	PA0 to PA6
	PORTB	PB0, PB1, PB3, PB5 to PB7	PB0 to PB7
	PORTC	PC0 to PC7	PC2 to PC7
	PORTD	_	PD0 to PD2
	PORTE	PE0 to PE7	PE0 to PE3
	PORTG		PG7
5 V tolerant	PORT1	P16, P17	P12, P13, P16, P17
	PORTA	PA6	
	PORTB	PB0	

Table 2-29 Comparison of I/O Port Registers

Register	Bit	RX111	RX140
PDR	B0 to B7	Pm0 to Pm7 direction control bits (m = 0 to 5, A to C, E, J)	Pm0 to Pm7 direction control bits (m = 0 to 5, A to E, G, H, J)
PODR	B0 to B7	Pm0 to Pm7 output data store bits (m = 0 to 5, A to C, E, J)	Pm0 to Pm7 output data store bits (m = 0 to 5, A to E, G, H, J)
PIDR	B0 to B7	Pm0 to Pm7 bits (m = 0 to 5, A to C, E, J)	Pm0 to Pm7 bits (m = 0 to 5, A to E, G, H, J)
PMR	B0 to B7	Pm0 pin mode control bits (m = 0 to 5, A to C, E, J) 0: Use pin as general I/O port. 1: Use pin as I/O port for peripheral function.	Pm0 pin mode control bits (m = 0 to 5, A to E, G, H, J) 0: Use pin as general I/O port. 1: Use pin as I/O port for peripheral function.
ODDo	D0 D4 D0	Day O. Day O. and Day O. and and the man	PG7 only 0: Use pin as general I/O port. 1: Use pin as I/O port for MD function (initial value).
ODR0	B0, B4, B6	Pm0, Pm2, and Pm3 output type select bits (m = 3, A to C, E)	Pm0, Pm2, and Pm3 output type select bits (m =1 to 3, A to E, J)
	B2, B3	Pm1 output type select bits (m = 3, A to C, E) • P31, PA1, PB1, and PC1	Pm1 output type select bits (m =1 to 3, A to E, J) • P21, P31, PA1, PB1, and
		b2 0: CMOS output 1: N-channel open-drain b3 This bit is read as 0. The write value should be 0.	PD1 b2 0: CMOS output 1: N-channel open-drain b3 This bit is read as 0. The write value should be 0.
		 PE1 b3 b2 0 0: CMOS output 0 1: N-channel open-drain 1 0: P-channel open-drain 1 1: Setting prohibited 	PE1 b3 b2 0 0: CMOS output 0 1: N-channel open-drain 1 0: P-channel open-drain 1 1: Hi-Z
ODR1	B0, B1 (RX111) B0 (RX140)	Pm4 output type select bits (m = 1, 2, A to C, E)	Pm4 output type select bits (m = 1 to 3, A to C, G)
		• PA4, PC4, and PE4 b0 0: CMOS output 1: N-channel open-drain b1 This bit is read as 0. The write value should be 0.	b0 0: CMOS output 1: N-channel open-drain
	D2 D4 D6	• P14 b1 b0 0 0: CMOS output 0 1: N-channel open-drain 1 0: P-channel open-drain 1 1: Setting prohibited	Dmf. Dmf. and Dm7 cutout turns
	B2, B4, B6	Pm5, Pm6, and Pm7 output type select bits (m = 1, 2, A to C, E)	Pm5, Pm6, and Pm7 output type select bits (m =1 to 3, A to C, G)
PCR	B0 to B7	Pm0 to Pm7 input pull-up resistor control bits (m = 0 to 3, 5, A to C, E)	Pm0 to Pm7 input pull-up resistor control bits (m = 0 to 5, A to E, G, H, J)
PRWCNTR		<u> </u>	Port read wait control register

2.16 Multi-Function Pin Controller

Table 2-30 is a comparison of the assignments of multiplexed pins, and Table 2-31 to Table 2-43 are comparisons of multi-function pin controller registers.

In the following comparison of the assignments of multiplexed pins, blue text designates pins that exist on the RX140 Group only and orange text pins that exist on the RX111 Group only. A circle (()) indicates that a function is assigned, a cross (\times) that the pin does not exist or that no function is assigned, and grayed out items mean that the function is not implemented.

Table 2-30 Comparison of Multiplexed Pin Assignments

Module/		Port	RX111		RX140	
Function	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Interrupt	NMI (input)	P35	0	0	0	0
	IRQ0 (input)	P30	0	×	0	0
		PE0	0	0	×	×
		PH1	X	×	0	0
	IRQ1 (input)	P31	0	×	0	0
		PE1	0	0	×	×
		PH2	X	×	0	0
	IRQ2 (input)	P32	0	×	0	×
		PB0	0	0	×	×
		PC4	0	0	×	×
		P36	X	×	0	0
	IRQ3 (input)	P27	0	0	×	×
		PE3	0	0	×	×
		PA6	0	0	×	×
	IRQ4 (input)	P14	0	0	0	0
		PB1	0	0	0	0
		PE4	0	0	×	×
		P37	X	×	0	0
	IRQ5 (input)	P15	0	0	0	0
		PA4	0	0	0	0
		PE5	0	×	0	×
	IRQ6 (input)	P16	0	0	0	0
		PA3	0	0	0	0
		PE6	0	×	×	×
	IRQ7 (input)	P17	0	0	0	0
		PE2	0	0	0	0
		PE7	0	0	×	×
Multi-function	MTIOC0A	P14	0	0	×	×
timer unit 2	(input/output)	PB3	0	0	0	0
		PE3	0	0	×	×
		PC4	X	×	0	0
	MTIOC0B	P15	0	0	0	0
	(input/output)	PA1	0	0	0	0
	MTIOC0C	P17	0	0	X	×
	(input/output)	P32	0	X	0	×
		PB0	0	0	X	×
		PB1	0	0	0	0
		PC5	X	X	0	0
	MTIOC0D (input/output)	PA3	0	0	0	0

Module/	Port RX111			RX140		
Function	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Multi-function	MTIOC1A	PE4	0	0	0	0
timer unit 2	(input/output)	PH3	X	×	×	X
	MTIOC1B	PA3	0	0	×	X
	(input/output)	PB5	0	0	0	0
		PE3	0	0	0	0
		PH0	X	×	×	X
	MTIOC2A	P26	0	0	0	0
	(input/output)	PA6	0	0	X	X
		PB5	0	0	0	0
		PE0	0	0	×	X
	MTIOC2B	P27	0	0	0	0
	(input/output)	PA4	O	0	X	X
		PE5	0	X	0	X
	MTIOC3A	P14	0	Ô	0	0
	(input/output)	P17	0	Ö	0	0
	(PC7	0	Ö	0	0
		PE4	0	0	X	X
	MTIOC3B	P17	0	0	Ô	Ô
	(input/output)	PA1	X	X	0	0
	(input/output)	PB3	0	$\frac{1}{0}$		_
			0	_	X	X
		PB7		X		X
		PC5	0	0	0	0
		PH0	X	X	0	0
	MTIOC3C	P16	0	0	0	0
	(input/output)	PC6	0	0	0	0
	MTIOC3D	P16	0	0	0	0
	(input/output)	PA6	X	X	0	0
		PB0	X	X	0	0
		PB6	0	X	0	X
		PC4	0	0	0	0
		PH1	X	X	0	0
	MTIOC4A	P55	×	×	0	X
	(input/output)	PA0	0	×	0	X
		PB3	0	0	0	0
		PE2	0	0	0	0
		PE4	×	×	0	0
	MTIOC4B	P30	0	X	0	0
	(input/output)	P54	0	X	0	X
		PC2	O	X	0	X
		PE3	O	0	0	0
	MTIOC4C	PA4	X	X	O	0
	(input/output)	PB1	Ô	Ô	0	0
		PE1	0	0	0	0
		PE5	0	X	0	×
		PH2	X	X		Ô
	MTIOC4D	P31	Ô	X	0	0
	(input/output)	P55	0	×	0	×
	(paroacpar)	PA3		X	0	Ô
		PC3	X		0	
				X		X
		PE4	0	0	0	0

Module/	ule/		RX111		RX140	
Function	Pin Function	Port Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Multi-function	MTIOC4D	PH3	X	X	0	0
timer unit 2	(input/output)					
	MTIC5U (input)	PA4	0	0	0	0
	MTIC5V (input)	PA6	0	0	0	0
		PA3	X	X	0	0
	MTIC5W (input)	PB0	0	0	0	0
	MTCLKA (input)	P14	0	0	0	0
		PA4	0	0	0	0
		PC6	0	0	0	0
	MTCLKB (input)	P15	0	0	0	0
		PA6	0	0	0	0
	MTCLICO (innuit)	PC7	0	0	0	0
	MTCLKC (input)	PA1 PC4	0	0	0	0
	MTCLKD (input)	PC4 PA3	0			0
	WITCLKD (Input)	PC5	0	0	0	0
Serial	RXD1 (input) /	P15	0	0	0	0
communications	SMISO1		_			_
interface	(input/output) /	P30	0	X	0	0
	SSCL1 (input/output)	PC6	0	0	×	×
	TXD1 (output) /	P16	0	0	0	0
	SMOSI1 (input/output) / SSDA1 (input/output)	P26	0	0	0	0
		PC7	0	0	X	×
	SCK1 (input/output)	P17	0	0	0	0
	Cort (inputoutput)	P27	0	0	0	0
		PC5	O	0	X	×
	CTS1# (input) /	P14	Ō	Ö	0	Ô
	RTS1# (output) / SS1# (input)	P31	0	×	0	0
	RXD5 (input) /	PA3	0	0	0	0
	SMISO5					
	(input/output) / SSCL5 (input/output)	PC2	0	×	0	×
	TXD5 (output) / SMOSI5	PA4	0	0	0	0
	(input/output) / SSDA5 (input/output)	PC3	0	×	0	×
	SCK5 (input/output)	PA1	0	0	0	0
		PC4	0	0	0	0
	CTS5# (input) / RTS5# (output) / SS5# (input)	PA6	0	0	0	0
	RXD6 (input) / SMISO6 (input/output) / SSCL6 (input/output)	PB0			*1	*1
	TXD6 (output) / SMOSI6	P32			O*1	×
	(input/output) / SSDA6 (input/output)	PB1			O*1	O*1
	SCK6 (input/output)	PB3			O*1	O*1

Module/		Port	RX111		RX140	
Function	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Serial	RXD8 (input) /	PC6	• • • • • • • • • • • • • • • • • • • •		O*1	O*1
communications	SMISO8	. 55				
interface	(input/output) /					
	SSCL8 (input/output)					
	TXD8 (output) /	PC7			O*1	O*1
	SMOSI8					
	(input/output) / SSDA8 (input/output)					
	SCK8 (input/output)	PC5			O*1	O*1
	CTS8# (input) /	PC5 PC4			O*1	O*1
	RTS8# (output) /	FC4				O ***
	SS8# (input)					
	RXD9 (input) /	PB6			O*1	×
	SMISO9	. 20				
	(input/output) /					
	SSCL9 (input/output)					
	TXD9 (output) /	PB7			O*1	×
	SMOSI9					
	(input/output) /					
	SSDA9 (input/output) SCK9 (input/output)	PB5			O*1	X
	CTS9# (input) /	PB4			O*1	X
	RTS9# (output) /	FD4 				^
	SS9# (input)					
	SCK12 (input/output)	PE0	0	0	0	×
	(P27	0	Ö	X	X
	RXD12 (input) /	PE2	0	0	0	O*3
	SMISO12					
	(input/output) /					
	SSCL12	P17	0	0	×	×
	(input/output) /					
	RXDX12 (input) TXD12 (output) /	PE1	0	0	0	O *4
	SMOSI12					
	(input/output) /					
	SSDA12					
	(input/output) /	P14	0	0	×	×
	TXDX12 (output) /					
	SIOX12 (input/output)					
	CTS12# (input) /	PE3	0	0	0	O *5
	RTS12# (output) / SS12# (input)					
I ² C bus interface	SCL0 (input/output)	P16	0	0	0	0
1-0 bus interrace	GOLO (III)	PB0	0	0	X	X
	SDA0 (input/output)	P17	0	0	0	0
	ODAO (iliparoatpat)	PA6	0	0	X	X
Serial peripheral	RSPCKA	P15	0	0	X	X
interface	(input/output)	PB0	0	0	0	0
	(is an a arisar)	PC5	0	0	0	0
		PE3	0	0	X	X
	MOSIA (input/output)	P16	0	0	 	1 0
	moon't (inputoutput)	PA6	0	0	0	0
		PE4	0	0	X	X
	l	·			1/	1/

Module/ Function		Port	RX111		RX140	
	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Serial peripheral	MOSIA (input/output)	PC6	0	0	0	0
_	MISOA (input/output)	P17	0	0	0	0
	, , , ,	PC7	0	0	0	0
		PA3	0	0	×	×
	SSLA0 (input/output)	P14	Ō	O	×	×
	(1 1 /	PA4	0	0	0	0
			0	0	0	0
	SSLA1 (output)	PA0	0	×	0	×
	SSLA2 (output)	PA1	0	0	0	0
	SSLA3 (output)	PC2	0	×	0	×
USB 2.0	USB0_EXICEN	PC6	0	0		
host/function	(output)					
module	USB0_VBUSEN	P16	0	0		
	(output)	PC4	0	0		
		P26	0	0		
	USB0_OVRCURA	P14	0	0		
	(input)	PB3	0	0		
	USB0_OVRCURB	P16	0	0		
	(input)	PC7	0	0		
	USB0_ID (input)	PC5	0	0		
	USB0_VBUS (input)	P16	0	0		
	USB0_VBUS (input) *7		0	0		
Realtime clock	RTCOUT (output)	P16	0	0	0	0
		P32	0	×	0	×
		PB0	0	0	×	×
		PA1	0	0	×	×
12-bit A/D	AN000 (input)*2	P40	0	0	0	0
converter	AN001 (input)*2	P41	0	0	0	0
	AN002 (input)*2	P42	0	0	0	0
	AN003 (input)*2	P43	0	×	0	×
	AN004 (input)*2	P44	0	×	0	×
	AN005 (input)*2	P45			0	0
	AN006 (input)*2	P46	0	0	0	0
	AN007 (input)*2	P47			0	0
Γ	AN008 (input)*2	PE0	0	0		
[AN009 (input)*2	PE1	0	0		
	AN010 (input)*2	PE2	0	0		
	AN011 (input)*2	PE3	0	0		
Ι Γ	AN012 (input)*2	PE4	0	0		
	AN013 (input)*2	PE5	0	X		
	AN014 (input)*2	PE6	0	X		
Ι Γ	AN015 (input)*2	PE7	0	0		
	AN016 (input)*2	PE0			0	×
	AN017 (input)*2	PE1			0	0
	AN018 (input)*2	PE2			0	0
	AN019 (input)*2	PE3			0	0
	AN020 (input)*2	PE4			0	0
	AN021 (input)*2	PE5			0	×

Module/ Function 12-bit A/D	Pin Function	Port	_			
12-bit A/D		Allocation	64-Pin	48-Pin	64-Pin	48-Pin
	VREFH0 (input)	PJ6	0	0		
converter	VREFL0 (input)	PJ7	0	0		
	ADTRG0# (input)	P16	0	0	0	0
		P27	0	0	×	X
		PB0	0	0	×	X
Clock	CLKOUT (output)	PE3	X	×	0	0
generation		PE4	X	×	0	0
circuit		PE4	X	×	0	0
		PE4	X	×	0	0
Clock frequency	CACREF (input)	P27	0	0	×	×
accuracy		PA0	0	×	0	X
measurement		PC7	0	0	0	0
circuit		PH0	0	0	0	0
Voltage	CMPA2 (input)*2	P27	0	0	×	×
detection circuit		PE4	X	×	0	0
Port output	POE0# (input)	PC4	0	0	0	0
enable 2		PA3	0	0	×	X
	POE1# (input)	PB5	0	0	0	0
	POE2# (input)	PA6	0	0	0	0
	POE3# (input)	PB3	0	0	0	0
	,	PE0	0	0	×	×
	POE8# (input)	P17	0	0	0	0
	· · /	P30	0	X	0	0
		PE3	0	0	0	0
8-bit timer	TMO0 (output)	PB3			0	0
		PH1			0	0
	TMCI0 (input)	PB1			0	0
		PH3			0	0
	TMRI0 (input)	PA4			0	0
		PH2			0	0
	TMO1 (output)	P17			0	0
		P26			0	0
	TMCI1 (input)	P54			0	×
	· · /	PC4			0	0
	TMRI1 (input)	PB5			0	0
	TMO2 (output)	P16			0	0
		PC7			0	0
	TMCI2 (input)	P15			0	0
	\ \ \	P31			0	0
		PC6			0	0
	TMRI2 (input)	P14			O	Ö
	V 1 /	PC5			Ö	O
8-bit timer	TMO3 (output)	P32			Ö	×
	V 1 2 7	P55			O	×
	TMCI3 (input)	P27			Ö	0
	V 1 7	PA6			Ö	0
	TMRI3 (input)	P30			Ö	0
Low-power	LPTO (output)	P26			0	0
timer	- ()	PB3			0	0
		PC7			0	0

Function CAN module	Pin Function CTXD0 (output)	Port Allocation	0.4 D'	40 D:		
CAN module	CTXD0 (output)		64-Pin	48-Pin	64-Pin	48-Pin
	OTADO (odipat)	P14			O*1	O *1
		P54			O*1	×
	CRXD0 (input)	P15			O*1	O*1
		P55			O*1	×
D/A converter	DA0 (output)*2	P03	0	×	0	×
	DA1 (output)*2	P05	0	×	0	×
Comparator B	CMPB0 (input)*2	PE1			0	0
	CVREFB0 (input)*2	PE2			0	0
	CMPOB0 (output)	PE5			0	×
	CMPB1 (input)*2	PA3			0	0
	CVREFB1 (input)*2	PA4			0	0
	CMPOB1 (output)	PB1			0	0
Capacitive	TS0 (input/output)	P32			O*1	×
touch sensing	TS1 (input/output)	P31			O*1	○ *1
unit	TS2 (input/output)	P30			O*1	O *1
	TS3 (input/output)	P27			0	0
	TS4 (input/output)	P26			0	0
	TS5 (input/output)	P15			O*1	O*1
	TS6 (input/output)	P14			O*1	○ *1
	TS7 (input/output)	PH3			O*1	O*1
	TS8 (input/output)	PH2			O*1	O*1
	TS9 (input/output)	PH1			O*1	O*1
	TS10 (input/output)	PH0			O*1	O *1
	TS11 (input/output)	P55			O*1	×
	TS12 (input/output)	P54			O*1	×
	TS13 (input/output)	PC7			0	0
	TS14 (input/output)	PC6			0	0
	TS15 (input/output)	PC5			0	0
	TS16 (input/output)	PC3			O*1	×
	TS17 (input/output)	PC2			O*1	×
	TS18 (input/output)	PB7			O*1	×
	TS19 (input/output)	PB6			O*1	×
	TS20 (input/output)	PB5			O*1	O *1
	TS22 (input/output)	PB3			O*1	O *1
	TS24 (input/output)	PB1			O*1	O *1
	TS25 (input/output)	PB0			0	0
	TS26 (input/output)	PA6			O*1	0
	TS28 (input/output)	PA4			0	0
	TS29 (input/output)	PA3			0	0
	TS31 (input/output)	PA1			0	0
	TS32 (input/output)	PA0			O*1	×
	TS33 (input/output)	PE4			0	0
	TS34 (input/output)	PE3			0	0
	TS35 (input/output)	PE2			0	0
	TSCAP (—)	PC4			0	0

Notes: 1. This function is not implemented on RX140 Group products with ROM capacity of 64 KB.

- 2. To use these pin functions, set the relevant pins as general I/O ports (PORT.PDR.Bm and PORT.PMR.Bm bits both cleared to 0).
- 3. The SMISO12 function is not implemented on 48-pin package products.
- 4. The SMOSI12 function is not implemented on 48-pin package products.

- 5. The SS12# function is not implemented on 48-pin package products.
- 6. 5 V tolerant.
- 7. Not 5 V tolerant.

Table 2-31 Comparison of P0n Pin Function Control Register (P0nPFS)

Register	Bit	RX111 (n = 3, 5)	RX140 (n = 3, 5, 7)
P0nPFS	PSEL[4:0]		Pin Function Select
	ASEL	Analog Function Select	Analog Function Select

Table 2-32 Comparison of P1n Pin Function Control Register (P1nPFS)

Register	Bit	RX111 (n = 4 to 7)	RX140 (n = 2 to 7)
P12PFS		_	P12 pin function control register
P13PFS		_	P13 pin function control register
P14PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3A
		00010b: MTCLKA	00010b: MTCLKA
		00011b: MTIOC0A	
			00101b: TMRI2
		01011b: CTS1#/RTS1#/SS1#	01011b: CTS1#/RTS1#/SS1#
		01100b: TXD12/SMOSI12/SSDA12/	
		TXD12/SIOX12	
		01101b: SSLA0	
			11001b: TS6
			11100b: CTXD0
P15PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0B	00001b: MTIOC0B
		00010b: MTCLKB	00010b: MTCLKB
			00101b: TMCI2
		01001b: CLKOUT	
		01010b: RXD1/SMISO1/SSCL1	01010b: RXD1/SMISO1/SSCL1
		01101b: RSPCKA	
			11001b: TS5
			11100b: CRXD0
P16PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3C
			00010b: MTIOC3D
			00101b: TMO2
		00111b: RTCOUT	00111b: RTCOUT
		01001b: ADTRG0#	01001b: ADTRG0#
		01010b: TXD1/SMOSI1/SSDA1	01010b: TXD1/SMOSI1/SSDA1
		01101b: MOSIA	01101b: MOSIA
		01111b: SCL0	01111b: SCL



Register	Bit	RX111 (n = 4 to 7)	RX140 (n = 2 to 7)
P17PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3A
			00010b: MTIOC3B
		00011b: MTIOC0C	
			00101b: TMO1
			00111b: POE8#
		01010b: SCK1	01010b: SCK1
		01100b: RXD12/SMISO12/	
		SSCL12/RXDX12	
		01101b: MISOA	01101b: MISOA
		01111b: SDA0	01111b: SDA0
P1nPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
			P12: IRQ2 (80-pin)
			P13: IRQ3 (80-pin)
		P14: IRQ4 (64/48/40/36-pin)	P14: IRQ4 (80/64/48-pin)
		P15: IRQ5 (64/48/40/36-pin)	P15: IRQ5 (80/64/48-pin)
		P16: IRQ6 (64/48/40/36-pin)	P16: IRQ6 (80/64/48/32-pin)
		P17: IRQ7 (64/48/40/36-pin)	P17: IRQ7 (80/64/48/32-pin)

Table 2-33 Comparison of P2n Pin Function Control Register (P2nPFS)

Register	Bit	RX111 (n = 6, 7)	RX140 (n = 0, 1, 6, 7)
P20PFS		_	P20 pin function control register
P21PFS		_	P21 pin function control register
P26PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		000001 111 7	000001 11: 7
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC2A	00001b: MTIOC2A
			00101b: TMO1
		01010b: TXD1/SMOSI1/SSDA1	01010b: TXD1/SMOSI1/SSDA1
			11001b: TS4
			11011b: LPTO
P27PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC2B	00001b: MTIOC2B
			00101b: TMCl3
		00111b: CACREF	
		01001b: ADTRG0#	
		01010b: SCK1	01010b: SCK1
		01100b: SCK12	
		01100b. SCR12	11001b: TS2
DO-DEC	IOFI	Intermed in put for ation and at 1.9	11001b: TS3
P2nPFS	ISEL	Interrupt input function select bit	_
	ASEL	Analog function select bit	—

Table 2-34 Comparison of P3n Pin Function Control Register (P3nPFS)

Register	Bit	RX111 (n = 0 to 2)	RX140 (n = 0 to 2, 4, 6, 7)
P30PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4B
			00101b: TMRI3
			00111b: POE8#
		01010b: RXD1/SMISO1/SSCL1	01010b: RXD1/SMISO1/SSCL1
			11001b: TS2
P31PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4D
		04.0446. 070#4/070#4/004#	00101b: TMCl2
		01011b: CTS#1/RTS#1/SS1#	01011b: CTS#1/RTS#1/SS1#
P32PFS	DCEL [4:0]	Pin function select bits	11001b: TS1 Pin function select bits
P32PF3	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0C	00001b: MTIOC0C
		000015. W110000	00101b: TMO3
		00111b: RTCOUT	00111b: RTCOUT
			01011b: TXD6/SMOSI6/SSDA6
			11001b: TS0
P34PFS		_	P34 pin function control register
P36PFS		_	P36 pin function control register
P37PFS		_	P37 pin function control register
P3nPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
		P30: IRQ0 (64-pin)	P30: IRQ0 (80/64/48/32-pin)
		P31: IRQ1 (64-pin)	P31: IRQ1 (80/64/48/32-pin)
		P32: IRQ2 (64-pin)	P32: IRQ2 (80/64-pin)
			P34: IRQ4 (80-pin)
			P36: IRQ2 (80/64/48/32-pin)
			P37: IRQ4 (80/64/48-pin)

Table 2-35 Comparison of P4n Pin Function Control Register (P4nPFS)

Register	Bit	RX111 (n = 0 to 4, 6)	RX140 (n = 0 to 7)
P4nPFS	ASEL	Analog function select bit	Analog function select bit
		0: Used as other than as analog pin	0: Used as other than as analog pin
		1: Used as analog pin	1: Used as analog pin
		P40: AN000 (64/48-pin)	P40: AN000 (80/64/48/32-pin)
		P41: AN001 (64/48/40/36-pin)	P41: AN001 (80/64/48/32-pin)
		P42: AN002 (64/48/40/36-pin)	P42: AN002 (80/64/48/32-pin)
		P43: AN003 (64-pin)	P43: AN003 (80/64-pin)
		P44: AN004 (64-pin)	P44: AN004 (80/64-pin)
			P45: AN005 (80/64/48-pin)
		P46: AN006 (64/48/40-pin)	P46: AN006 (80/64/48-pin)
			P47: AN007 (80/64/48-pin)

Table 2-36 Comparison of P5n Pin Function Control Register (P5nPFS)

Register	Bit	RX111	RX140 (n = 4, 5)
P5nPFS		_	P5n pin function control register

Table 2-37 Comparison of PAn Pin Function Control Register (PAnPFS)

Register	Bit	RX111 (n = 0, 1, 3, 4, 6)	RX140 (n = 0 to 6)
PA0PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4A
		00111b: CACREF	00111b: CACREF
		01101b: SSLA1	01101b: SSLA1
			11001b: TS32
PA1PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0B	00001b: MTIOC0B
		00010b: MTCLKC	00010b: MTCLKC
			00011b: MTIOC3B
		00111b: RTCOUT	
		01010b: SCK5	01010b: SCK5
		01101b: SSLA2	01101b: SSLA2
			11001b: TS31
PA2PFS		_	PA2 pin function control register
PA3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0D	00001b: MTIOC0D
		00010b: MTCLKD	00010b: MTCLKD
		00011b: MTIOC1B	00011b: MTIOC4D
			00100b: MTIC5V
		01010b: RXD5/SMISO5/SSCL5	01010b: RXD5/SMISO5/SSCL5
		01101b: MISOA	
			11001b: TS29

Register	Bit	RX111 (n = 0, 1, 3, 4, 6)	RX140 (n = 0 to 6)
PA4PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIC5U	00001b: MTIC5U
		00010b: MTCLKA	00010b: MTCLKA
		00011b: MTIOC2B	00011b: MTIOC4C
			00101b: TMRI0
		01010b: TXD5/SMOSI5/SSDA5	01010b: TXD5/SMOSI5/SSDA5
		01101b: SSLA0	01101b: SSLA0
			11001b: TS28
PA5PFS		_	PA5 pin function control register
PA6PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIC5V	00001b: MTIC5V
		00010b: MTCLKB	00010b: MTCLKB
		00011b: MTIOC2A	00011b: MTIOC3D
			00101b: TMCl3
			00111b: POE2#
		01011b: CTS5#/RTS5#/SS5#	01011b: CTS5#/RTS5#/SS5#
		01101b: MOSIA	01101b: MOSIA
		01111b: SDA0	
			11001b: TS26
PAnPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
		PA3: IRQ6 (64/48/40/36-pin)	PA3: IRQ6 (80/64/48/32-pin)
		PA4: IRQ5 (64/48/40/36-pin)	PA4: IRQ5 (80/64/48/32-pin)
		PA6: IRQ3 (64/48/40/36-pin)	
	ASEL	_	Analog function select bit

Table 2-38 Comparison of PBn Pin Function Control Register (PBnPFS)

Register	Bit	RX111 (n = 0, 1, 3, 5 to 7)	RX140 (n = 0 to 7)
PB0PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIC5W	00001b: MTIC5W
		00010b: MTIOC0C	00010b: MTIOC3D
		00111b: RTCOUT	
		01001b: ADTRG0#	
			01011b: RXD6/SMISO6/SSCL6
		01101b: RSPCKA	01101b: RSPCKA
		01111b: SCL0	
			11001b: TS25

Register	Bit	RX111 (n = 0, 1, 3, 5 to 7)	RX140 (n = 0 to 7)
PB1PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0C	00001b: MTIOC0C
			00010b: MTIOC4C
			00101b: TMCI0
			01011b: TXD6/SMOSI6/SSDA6
			10000b: CMPOB1
			11001b: TS24
PB2PFS	_	_	PB2 pin function control register
PB3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0A	00001b: MTIOC0A
			00010b: MTIOC4A
			00101b: TMO0
			00111b: POE3#
			01011b: SCK6
			11001b: TS22
			11011b: LPTO
PB4PFS		_	PB4 pin function control register
PB5PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC2A	00001b: MTIOC2A
		00010b: MTIOC1B	00010b: MTIOC1B
			00101b: TMRI1
			00111b: POE1#
			01010b: SCK9
			11001b: TS20
PB6PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3D
			01010b: RXD9/SMISO9/SSCL9
			11001b: TS19
PB7PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3B
			01010b: TXD9/SMOSI9/SSDA9
			11001b: TS18
PBnPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
			' '
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
		PB0: IRQ2 (64/48/40/36-pin)	· ·
		PB1: IRQ4 (64/48-pin)	PB1: IRQ4 (80/64/48-pin)
1	1	· ' '	

Table 2-39 Comparison of PCn Pin Function Control Register (PCnPFS)

Register	Bit	RX111 (n = 2 to 7)	RX140 (n = 2 to 7)
PC2PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4B
		01010b: RXD5/SMISO5/SSCL5	01010b: RXD5/SMISO5/SSCL5
		01101b: SSLA3	01101b: SSLA3
			11001b: TS17
PC3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		000001.11: 7	000006.11: 7
		00000b: Hi-Z	00000b: Hi-Z
		04040h, TVDE/SMOSIE/SSDAE	00001b: MTIOC4D
		01010b: TXD5/SMOSI5/SSDA5	01010b: TXD5/SMOSI5/SSDA5 11001b: TS16
PC4PFS	DCEL [4:0]	Pin function select bits	Pin function select bits
PC4PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		000005.1112	00001b: MTIOC3D
		00010b: MTCLKC	00010b: MTCLKC
		OCCUPATION OF THE STATE OF THE	00011b: MTIOC0A
			00101b: TMCI1
			00111b: POE0#
		01001b: CLKOUT	00111211 02011
		01010b: SCK5	01010b: SCK5
			01011b: CTS8#/RTS8#/SS8#
		01101b: SSLA0	01101b: SSLA0
			11001b: TSCAP
PC5PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3B
		00010b: MTCLKD	00010b: MTCLKD
			00011b: MTIOC0C
			00101b: TMRI2
			01010b: SCK8
		01011b: SCK1	
		01101b: RSPCKA	01101b: RSPCKA
			11001b: TS15
PC6PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		accept MTC: 10	00001b: MTIOC3C
		00010b: MTCLKA	00010b: MTCLKA
			00101b: TMCl2
		040445 - DVD4/084304/00014	01010b: RXD8/SMISO8/SSCL8
		01011b: RXD1/SMISO1/SSCL1	044045 MOCIA
		01101b: MOSIA	01101b: MOSIA
		<u> </u>	11001b: TS14

Register	Bit	RX111 (n = 2 to 7)	RX140 (n = 2 to 7)
PC7PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3A
		00010b: MTCLKB	00010b: MTCLKB
			00101b: TMO2
		00111b: CACREF	00111b: CACREF
			01010b: TXD8/SMOSI8/SSDA8
		01011b: TXD1/SMOSI1/SSDA1	
		01101b: MISOA	01101b: MISOA
			11001b: TS13
			11011b: LPTO
PCnPFS	ISEL	Interrupt input function select bit	_

Table 2-40 Comparison of PDn Pin Function Control Register (PDnPFS)

Register	Bit	RX111	RX140 (n = 0 to 2)
PDnPFS		_	PDn pin function control register

Table 2-41 Comparison of PEn Pin Function Control Register (PEnPFS)

Register	Bit	RX111 (n = 0 to 7)	RX140 (n = 0 to 5)
PE0PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00010b: MTIOC2A	
_		01100b: SCK12	01100b: SCK12
PE1PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		200001 11: 7	200001 11: 7
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4C
		01100b: TXD12/SMOSI12/SSDA12/ TXDX12/SIOX12	01100b: TXD12/SMOSI12/SSDA12/ TXDX12/SIOX12
DEADEC	DCEL [4:0]	i	Pin function select bits
PE2PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		000000.1112	00001b: MTIOC4A
		01100b: RXD12/SMISO12/	01100b: RXD12/SMISO12/
		SSCL12/RXDX12	SSCL12/RXDX12
			11001b: TS35
PE3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC1B	00001b: MTIOC4B
			00010b: MTIOC1B
		00011b: MTIOC0A	
			00111b: POE8#
			01001b: CLKOUT
		01100b: CTS12#/RTS12#/SS12#	01100b: CTS12#/RTS12#/SS12#
		01101b: RSPCKA	
			11001b: TS34

Register	Bit	RX111 (n = 0 to 7)	RX140 (n = 0 to 5)
PE4PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4D
		00010b: MTIOC1A	00010b: MTIOC1A
			00011b: MTIOC4A
			01001b: CLKOUT
		01101b: MOSIA	
			11001b: TS33
PE5PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4C
		00010b: MTIOC2B	00010b: MTIOC2B
			10000b: CMPOB0
PE6PFS	_	PE6 pin function control register	_
PE7PFS	_	PE7 pin function control register	_
PEnPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
		PE0: IRQ0 (64/48/40/36-pin)	
		PE1: IRQ1 (64/48/40/36-pin)	
		PE2: IRQ7 (64/48/40/36-pin)	PE2: IRQ7 (80/64/48/32-pin)
		PE3: IRQ3 (64/48/40/36-pin)	
		PE4: IRQ4 (64/48/40/36-pin)	
		PE5: IRQ5 (64-pin)	PE5: IRQ5 (80/64-pin)
		PE6: IRQ6 (64-pin)	
		PE7: IRQ7 (64/48-pin)	
	ASEL	Analog function select bit	Analog function select bit
		0: Used as other than as analog pin	0: Used as other than as analog pin
		1: Used as analog pin	1: Used as analog pin
		PE0: AN008 (64/48/40/36-pin)	PE0: AN016 (80/64-pin)
		PE1: AN009 (64/48/40/36-pin)	PE1: AN017, CMPB0
			(80/64/48/32-pin)
		PE2: AN010 (64/48/40/36-pin)	PE2: AN018, CVREFB0
			(80/64/48/32-pin)
		PE3: AN011 (64/48/40/36-pin)	PE3: AN019 (80/64/48/32-pin)
		PE4: AN012 (64/48/40/36-pin)	PE4: AN020, CMPA2
		DEE ANIO40 (04 :)	(80/64/48/32-pin)
		PE5: AN013 (64-pin)	PE5: AN021 (80/64-pin)
		PE6: AN014 (64-pin)	
		PE7: AN015 (64/48-pin)	

Table 2-42 Comparison of PHn Pin Function Control Register (PHnPFS)

Register	Bit	RX111	RX140 (n = 0 to 3)
PH0PFS		_	PHn1 pin function control register

Table 2-43 Comparison of PJn Pin Function Control Register (PJnPFS)

Register	Bit	RX111 (n = 6, 7)	RX140 (n = 1, 6, 7)
PJ1PFS		_	PJ1 pin function control register
PJ6PFS	ASEL	Analog function select bit	Analog function select bit
		0: The AVCC0 pin is selected as the reference power supply pin for the high-potential side.	0: Used as other than as analog pin
		1: The VREFH0 pin is selected as the reference power supply pin for the high-potential side.	1: Used as analog pin
			PJ6: VREFH0 (80/64/48-pin)
PJ7PFS	ASEL	Analog function select bit	Analog function select bit
		0: The AVSS0 pin is selected as the reference power supply ground pin for the low-potential side.	0: Used as other than as analog pin
		1: The VREFL0 pin is selected as the reference power supply ground pin for the low-potential side.	1: Used as analog pin
			PJ7: VREFL0 (80/64/48-pin)

2.17 Realtime Clock

Table 2-44 is a comparison of realtime clock registers.

Table 2-44 Comparison of Realtime Clock Registers

Register	Bit	RX111 (RTCA)	RX140 (RTCB)
RCR3		RTC control register 3	

2.18 Serial Communications Interface

Table 2-45 is a comparative overview of the serial communications interfaces, and Table 2-46 is a comparison of serial communications interface channel specifications, and Table 2-47 is a comparison of serial communications interface registers.

Table 2-45 Comparative Overview of Serial Communications Interfaces

Item		RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Number of channels		SCIe: 2 channelsSCIf: 1 channel	 SClg: 3 channels SClk: 2 channels SClh: 1 channel
Serial communications modes		 Asynchronous Clock synchronous Smart card interface Simple I²C bus Simple SPI bus 	 Asynchronous Clock synchronous Smart card interface Simple I²C bus Simple SPI bus
Transfer speed		Bit rate specifiable by on-chip baud rate generator.	Bit rate specifiable by on-chip baud rate generator.
Full-duplex communication		 Transmitter: Continuous transmission possible using double- buffer structure. Receiver: Continuous reception possible using double- buffer structure. 	 Transmitter: Continuous transmission possible using double- buffer structure. Receiver: Continuous reception possible using double- buffer structure.
Data transfer		Selectable as LSB first or MSB first transfer.	Selectable as LSB first or MSB first transfer.
I/O signal level	inversion	_	The levels of input and output signals can be inverted independently (SCI1 and SCI5).
Interrupt source	S	Transmit end, transmit data empty, receive data full, and receive error, completion of generation of a start condition, restart condition, or stop condition (for simple I ² C mode)	Transmit end, transmit data empty, receive data full, receive error, and data match (SCI1 and SCI5), completion of generation of a start condition, restart condition, or stop condition (for simple I ² C mode)
Low power cons	sumption function	Individual channels can be transitioned to the module stop state.	Individual channels can be transitioned to the module stop state.
Asynchronous	Data length	7 or 8 bits	7, 8, or 9 bits
mode	Transmission stop bits	1 or 2 bits	1 or 2 bits
	Parity	Even parity, odd parity, or no parity	Even parity, odd parity, or no parity
	Receive error detection function	Parity, overrun, and framing errors	Parity, overrun, and framing errors
	Hardware flow control	CTSn# and RTSn# pins can be used in controlling transmission/reception.	CTSn# and RTSn# pins can be used in controlling transmission/reception.

Item		RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Asynchronous mode	Data match detection		Compares receive data and comparison data, and generates interrupt when they are matched (SCI1 and SCI5)
	Start-bit detection	Low level or falling edge is selectable.	Low level or falling edge is selectable.
	Receive data sampling timing adjustment		The receive data sampling point can be shifted from the center of the data forward or backward to a base point (SCI1 and SCI5).
	Transmit signal change timing adjustment		Either the falling or rising edge of the transmit data can be delayed (SCI1 and SCI5).
	Break detection	When a framing error occurs, a break can be detected by reading the RXDn pin level directly.	When a framing error occurs, a break can be detected by reading the RXDn pin level directly or by reading the SPTR.RXDMON flag (SCI1 or SCI5).
	Clock source	 An internal or external clock can be selected. Transfer rate clock input from the TMR can be used (SCI1, SCI5, and SCI12). 	 An internal or external clock can be selected. Transfer rate clock input from the TMR can be used (SCI5, SCI6, and SCI12).
	Double-speed mode		Baud rate generator double-speed mode is selectable.
	Multi-processor communications function	Serial communication among multiple processors	Serial communication among multiple processors
	Noise cancellation	The signal paths from input on the RXDn pins incorporate digital noise filters.	The signal paths from input on the RXDn pins incorporate digital noise filters.
Clock	Data length	8 bits	8 bits
synchronous mode	Receive error detection	Overrun error	Overrun error
	Hardware flow control	CTSn# and RTSn# pins can be used in controlling transmission/ reception.	CTSn# and RTSn# pins can be used in controlling transmission/ reception.
Smart card interface mode	Error processing	 An error signal can be automatically transmitted when detecting a parity error during reception Data can be automatically retransmitted when receiving an error signal during transmission 	 An error signal can be automatically transmitted when detecting a parity error during reception Data can be automatically retransmitted when receiving an error signal during transmission
	Data type	Both direct convention and inverse convention are supported.	Both direct convention and inverse convention are supported.
Simple I ² C mode	Communication format	I ² C bus format	I ² C bus format
	Operating mode	Master (single-master operation only)	Master (single-master operation only)
	Transfer rate	Fast mode is supported.	Fast mode is supported.

Item		RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Simple I ² C mode	Noise cancellation	The signal paths from input on the SSCLn and SSDAn pins incorporate digital noise filters, and the interval for noise cancellation is adjustable.	The signal paths from input on the SSCLn and SSDAn pins incorporate digital noise filters, and the interval for noise cancellation is adjustable.
Simple SPI	Data length	8 bits	8 bits
mode	Detection of errors	Overrun error	Overrun error
	SS input pin function	Applying the high level to the SSn# pin can cause the output pins to enter the high-impedance state.	Applying the high level to the SSn# pin can cause the output pins to enter the high-impedance state.
	Clock settings	Four kinds of settings for clock phase and clock polarity are selectable.	Four kinds of settings for clock phase and clock polarity are selectable.
Extended serial mode (supported by SCI12 only)	Start frame transmission	 Break field low width output and generation of interrupt on completion Detection of bus collision and generation of interrupt on detection 	 Break field low width output and generation of interrupt on completion Detection of bus collision and generation of interrupt on detection
	Start frame reception	 Detection of break field low width and generation of interrupt on detection Data comparison of control fields 0 and 1 and generation of interrupt when they match Ability to specify two kinds of data for comparison (primary and secondary) in control field 1 Ability to specify priority interrupt bit in control field 1 Support for start frames that do not include a break field Support for start frames that do not include a control field 0 Function for measuring bit rates 	 Detection of break field low width and generation of interrupt on detection Data comparison of control fields 0 and 1 and generation of interrupt when they match Ability to specify two kinds of data for comparison (primary and secondary) in control field 1 Ability to specify priority interrupt bit in control field 1 Support for start frames that do not include a break field Support for start frames that do not include a control field 0 Function for measuring bit rates

Item		RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
	I/O control function	 Ability to select polarity or TXDX12 and RXDX12 signals Ability to specify digital filtering of RXDX12 signal Half-duplex operation employing RXDX12 and TXDX12 signals multiplexed on the same pin Ability to select receive data sampling timing of RXDX12 pin 	 Ability to select polarity or TXDX12 and RXDX12 signals Ability to specify digital filtering of RXDX12 signal Half-duplex operation employing RXDX12 and TXDX12 signals multiplexed on the same pin Ability to select receive data sampling timing of RXDX12 pin
	Timer function	Usable as reloading timer	Usable as reloading timer
Bit rate modulati	ion function		Correction of outputs from the on-chip baud rate generator can reduce errors.
Event link function (supported by SCI5 only)		 Error (receive error or error signal detection) event output Receive data full event output Transmit data empty event output Transmit end event output 	 Error (receive error or error signal detection) event output Receive data full event output Transmit data empty event output Transmit end event output

Table 2-46 Comparison of Serial Communications Interface Channel Specifications

Item	RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Synchronous mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Clock synchronous mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Smart card interface mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Simple I ² C mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Simple SPI mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Data match detection	_	SCI1, SCI5
Extended serial mode	SCI12	SCI12
MTU clock input (RX111)	SCI1, SCI5, SCI12	SCI5, SCI6, SCI12
TMR clock input (RX140)		
Event link function	SCI5	SCI5
Peripheral module clock	PCLKB:	PCLKB:
	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12

Table 2-47 Comparison of Serial Communications Interface Registers

Register	Bit	RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
RDRH	—	_	Receive data registers H, L, and HL
RDRL			
RDRHL			
TDRH	_	_	Transmit data registers H, L, and HL
TDRL			
TDRHL			

Register	Bit	RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
SMR	CHR	Character length bit	Character length bit
		(Valid only in asynchronous mode)	(Valid only in asynchronous mode) Selections are made in combination with the SCMR.CHR1 bit.
		Selects 8 bits as the data length for transmission and reception Selects 7 bits as the data length for transmission and reception	CHR1 CHR 0 0: Selects 9 bits as the data length for transmission and reception 0 1: Selects 9 bits as the data length for transmission and reception 1 0: Selects 8 bits as the data length for transmission and reception (initial value) 1 1: Selects 7 bits as the data length for transmission and reception
SCR	CKE[1:0]	Clock enable bits	Clock enable bits
(when SCMR.SMIF = 0)		 (Asynchronous mode) b1 b0 0 0: On-chip baud rate generator The SCKn pin can be used as an I/O port by means of an I/O port setting. 0 1: On-chip baud rate generator A clock with the same frequency as the bit rate is output on the SCKn pin. 1 x: External clock or MTU clock • When using an external clock, input a clock with a frequency 16 times the bit rate on the SCKn pin. When the SEMR.ABCS bit is set to 1, input a clock with a frequency eight times the bit rate. • The MTU clock can be used. When using the MTU clock, the SCKn pin can be used as an I/O port by means of an I/O port setting. 	 (Asynchronous mode) b1 b0 0 0: On-chip baud rate generator The SCKn pin is in the high- impedance state. 0 1: On-chip baud rate generator A clock with the same frequency as the bit rate is output on the SCKn pin. 1 x: External clock or TMR clock*1 When using an external clock, input a clock with a frequency 16 times the bit rate on the SCKn pin. When the SEMR.ABCS bit is set to 1, input a clock with a frequency eight times the bit rate. When using the TMR clock, the SCKn pin is in the high- impedance state.
		(Clock synchronous mode) b1 b0 0 x: Internal clock: The SCKn pin functions as the clock output pin. 1 x: External clock: The SCKn pin functions as the clock input pin.	(Clock synchronous mode) b1 b0 0 x: Internal clock: The SCKn pin functions as the clock output pin. 1 x: External clock: The SCKn pin functions as the clock input pin.

Register	Bit	RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
	MPIE	Multi-processor interrupt enable bit	Multi-processor interrupt enable bit
		(Valid in asynchronous mode when SMR.MP bit = 1) 0: Normal receive operation 1: When data is received while the multi-processor bit is set to 0, the data is skipped, and setting (to 1) of status flags ORER, and FER in SSR is disabled. When data is received while the multi-processor bit is set to 1, the MPIE bit is automatically cleared to 0, and normal receive operation resumes.	(Valid in asynchronous mode when SMR.MP bit = 1) 0: Normal receive operation 1: When data is received while the multi-processor bit is set to 0, the data is skipped, and setting (to 1) of status flags RDRF, ORER, and FER in SSR is disabled. When data is received while the multi-processor bit is set to 1, the MPIE bit is automatically cleared to 0, and normal receive operation resumes.
SCR	CKE[1:0]	Clock enable bits	Clock enable bits
(when SCMR.SMIF = 1)		(When the SMR.GM bit = 0) b1 b0 0 0: Output disabled (The SCKn pin can be used as an I/O port by means of an I/O port setting.) 0 1: Clock output 1 x: (Setting prohibited) (When the SMR.GM bit = 1) b1 b0 0 0: Low-level output fixed x 1: Clock output	 (When the SMR.GM bit = 0) b1 b0 0 0: Output disabled The SCKn pin is in the high-impedance state. 0 1: Clock output 1 x: Setting prohibited (When the SMR.GM bit = 1) b1 b0 0 0: Low-level output fixed x 1: Clock output 1 0: High-level output fixed
SCMR	CHR1	1 0: High-level output fixed	·
MDDR	CUKI		Character length bit Modulation duty register
		Asynchronous mode clock source	, ,
SEMR	ACS0	Asynchronous mode clock source select bit (Valid only in asynchronous mode) 0: External clock 1: Logical AND of two compare matches output from MTU	Asynchronous mode clock source select bit (Valid only in asynchronous mode) 0: External clock 1: Logical AND of two compare matches output from TMR (valid for SCI5, SCI6, and SCI12 only) The compare match outputs that can be used differ according to the SCI channel. Immediate transmission enable bit
	BRME	_	Bit rate modulation enable bit
	ABCSE		Asynchronous basic clock select extended bit
	BGDM	_	Baud rate generator double-speed mode select bit

Register	Bit	RX111 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
SPMR	MSS	Master slave select bit	Master slave select bit
CDR		0: TXDn pin: transmission, RXDn pin: reception (master mode) 1: TXDn pin: reception, RXDn pin: transmission (slave mode)	O: SMOSIn pin: transmission, SMISOn pin: reception (master mode) 1: SMOSIn pin: reception, SMISOn pin: transmission (slave mode) Comparison data register
DCCR			Data comparison control register
SPTR		_	Serial port register
TMGR	_	_	Transmit/receive timing select register
CR2	BCCS[1:0]	Bus collision detection clock select bits	Bus collision detection clock select bits
		b5 b4 0 0: SCI base clock 0 1: SCI base clock frequency divided by 2 1 0: SCI base clock frequency divided by 4 1 1: Setting prohibited	(When the SEMR.BGDM bit is cleared to 0 or the SEMR.BGDM bit is set to 1 and the SMR.CKS[1:0] bits are set to a value other than 00b) b5 b4 0 0: Base clock frequency divided by 2 1 0: Base clock frequency divided by 4 1 1: Setting prohibited (When the SEMR.BGDM bit is set to 1 and the SMR.CKS[1:0] bits are set to 00b) b5 b4 0 0: Base clock frequency divided by 2 0 1: Base clock frequency divided by 4 1 0: Setting prohibited

Note: 1. Selectable on SCI5, SCI6, and SCI12 only.

2.19 I²C bus Interface

Table 2-48 is a comparative overview of the I^2C bus interfaces, and Table 2-49 is a comparison of I^2C bus interface registers.

Table 2-48 Comparative Overview of I²C Bus Interfaces

Item	RX111 (RIIC)	RX140 (RIICa)
Communication format	 I²C bus format or SMBus format Selectable between master mode or slave mode. Automatic securing of the various setup times, hold times, and busfree times for the transfer rate 	 I²C bus format or SMBus format Selectable between master mode or slave mode. Automatic securing of the various setup times, hold times, and busfree times for the transfer rate
Transfer speed	Fast mode is supported (up to 400 kbps).	Fast mode is supported (up to 400 kbps).
Serial clock (SCL)	For master operation, the duty cycle of the SCL clock is selectable in the range from 4% to 96%.	For master operation, the duty cycle of the SCL clock is selectable in the range from 4% to 96%.
Issuing and detection conditions	 Start, restart, and stop conditions are generated automatically. Start conditions (including restart conditions) and stop conditions are detectable. 	 Start, restart, and stop conditions are generated automatically. Start conditions (including restart conditions) and stop conditions are detectable.
Slave addresses	 Up to three different slave addresses can be set. 7-bit and 10-bit address formats are supported (along with the use of both at once). General call addresses, device ID addresses, and SMBus host addresses are detectable. 	 Up to three different slave addresses can be set. 7-bit and 10-bit address formats are supported (along with the use of both at once). General call addresses, device ID addresses, and SMBus host addresses are detectable.
Acknowledgement	 For transmission, the acknowledge bit is loaded automatically. Transfer of the next data for transmission can be suspended automatically on reception of a not- acknowledge bit. For reception, the acknowledge bit is transmitted automatically. If a wait between the eighth and ninth clock cycles has been selected, software control of the value in the acknowledge field in response to the received value is possible. 	 For transmission, the acknowledge bit is loaded automatically. Transfer of the next data for transmission can be suspended automatically on reception of a not-acknowledge bit. For reception, the acknowledge bit is transmitted automatically. If a wait between the eighth and ninth clock cycles has been selected, software control of the value in the acknowledge field in response to the received value is possible.
Wait function	For reception, the following wait periods can be obtained by holding the SCL clock at the low level: Wait between the eighth and ninth clock cycles Wait between the ninth and first clock cycles	For reception, the following wait periods can be obtained by holding the SCL line at the low level: • Wait between the eighth and ninth clock cycles • Wait between the ninth and first clock cycles
SDA output delay function	Timing of the output of transmitted data, including the acknowledge bit, can be delayed.	Timing of the output of transmitted data, including the acknowledge bit, can be delayed.

Item	RX111 (RIIC)	RX140 (RIICa)
Timeout detection function	 Multi-master support Operation to synchronize the SCL clock in cases of conflict with the SCL clock from another master is possible. When issuing a start condition, loss of arbitration is detected by testing for non-matching of the signals for the SDA line. In master operation, loss of arbitration is detected by testing for non-matching of transmit data. Loss of arbitration due to detection of a start condition while the bus is busy is detectable (to prevent the issuing of double start conditions). Loss of arbitration in transfer of a not-acknowledge bit due to the signals for the SDA line not matching is detectable. Loss of arbitration due to non-matching of data is detectable in slave transmission. The internal timeout function is capable of detecting long-interval stop of the SCL 	 Multi-master support Operation to synchronize the SCL clock in cases of conflict with the SCL clock from another master is possible. When issuing a start condition, loss of arbitration is detected by testing for non-matching of the signals for the SDA line. In master operation, loss of arbitration is detected by testing for non-matching of transmit data. Loss of arbitration due to detection of a start condition while the bus is busy is detectable (to prevent the issuing of double start conditions). Loss of arbitration in transfer of a not-acknowledge bit due to the signals for the SDA line not matching is detectable. Loss of arbitration due to non-matching of data is detectable in slave transmission. The internal timeout function is capable of detecting long-interval stop of the SCL
Noise canceler	clock. The interface incorporates digital noise filters for both the SCL and SDA inputs, and the bandwidth for noise cancellation by the filters is adjustable by software.	The interface incorporates digital noise filters for both the SCL and SDA inputs, and the bandwidth for noise cancellation by the filters is adjustable by software.
Interrupt sources	Four sources:	Four sources:
consumption function	,	
RIIC operating modes	Four modes: Master transmit mode Master receive mode Slave transmit mode Slave receive mode	Four modes:

Item	RX111 (RIIC)	RX140 (RIICa)
Event link function	Four sources (RIIC0):	Four sources (RIIC0):
(output)	 Error in transfer or occurrence of events Detection of arbitration loss, NACK, timeout, a start condition including a restart condition, or a stop condition 	 Error in transfer or occurrence of events Detection of arbitration loss, NACK, timeout, a start condition including a restart condition, or a stop condition
	Receive data full (including matching with a slave address) Transmit data empty (including matching with a slave address) Transmit end	 Receive data full (including matching with a slave address) Transmit data empty (including matching with a slave address) Transmit end

Table 2-49 Comparison of I²C Bus Interface Registers

Register	Bit	RX111 (RIIC)	RX140 (RIICa)
ICMR2	TMWE	Timeout internal counter write enable bit	_
TMOCNTL TMOCNTU	_	Timeout internal counter	_

2.20 Serial Peripheral Interface

Table 2-50 is a comparative overview of serial peripheral interfaces, and Table 2-51 is a comparison of serial peripheral interface registers.

Table 2-50 Comparative Overview of Serial Peripheral Interfaces

Item	RX111 (RSPI)	RX140 (RSPIc)
Number of channels	1 channel	1 channel
RSPI transfer functions	 Use of MOSI (master out/slave in), MISO (master in/slave out), SSL (slave select), and RSPCK (RSPI clock) signals allows serial communications through SPI operation (4-wire method) or clock synchronous operation (3-wire method). Transmit-only operation is available. Communication mode: Full-duplex or transmit-only can be selected. Switching of the polarity of RSPCK Switching of the phase of RSPCK 	 Use of MOSI (master out/slave in), MISO (master in/slave out), SSL (slave select), and RSPCK (RSPI clock) signals allows serial communications through SPI operation (4-wire method) or clock synchronous operation (3-wire method). Communication mode: Full-duplex or transmit-only can be selected. Switching of the polarity of RSPCK Switching of the phase of RSPCK
Data format	 MSB first/LSB first selectable Transfer bit length is selectable as 8, 9, 10, 11, 12, 13, 14, 15, 16, 20, 24, or 32 bits. 128-bit transmit/receive buffers Up to four frames can be transferred in one round of transmission/reception (each frame consisting of up to 32 bits). 	 MSB first/LSB first selectable Transfer bit length is selectable as 8, 9, 10, 11, 12, 13, 14, 15, 16, 20, 24, or 32 bits. 128-bit transmit/receive buffers Up to four frames can be transferred in one round of transmission/reception (each frame consisting of up to 32 bits). Byte swapping of transmit and receive data is selectable
Bit rate	 In master mode, the on-chip baud rate generator generates RSPCK by frequency-dividing PCLK (the division ratio ranges from divided by 2 to divided by 4096). In slave mode, the minimum PCLK clock divided by 8 can be input as RSPCK (the maximum frequency of RSPCK is that of PCLK divided by 8). Width at high level: 4 cycles of PCLK Width at low level: 4 cycles of PCLK 	 In master mode, the on-chip baud rate generator generates RSPCK by frequency-dividing PCLK (the division ratio ranges from divided by 2 to divided by 4096). In slave mode, the minimum PCLK clock divided by 4 can be input as RSPCK (the maximum frequency of RSPCK is that of PCLK divided by 4). Width at high level: 2 cycles of PCLK Width at low level: 2 cycles of PCLK

Item	RX111 (RSPI)	RX140 (RSPIc)
Buffer configuration	Double buffer configuration for	Double buffer configuration for
	the transmit/receive buffers	the transmit/receive buffers
	128 bits for the transmit/receive	128 bits for the transmit/receive
Error detection	buffers	buffers
Enorgetection	Mode fault error detection Overrup error detection	Mode fault error detection
	Overrun error detection	Overrun error detection
	Parity error detection	Parity error detection
SSL control function	Fave COL 15:00 (COL 10.15	Underrun error detection Faut COL ping (COL AC to
SSL control function	 Four SSL pins (SSLA0 to SSLA3) for each channel 	 Four SSL pins (SSLA0 to SSLA3) for each channel
	1 1 1 1 1 00 100	In single-master mode, SSLA0 to
	• In single-master mode, SSLA0 to SSLA3 pins are output.	SSLA3 pins are output.
	In multi-master mode:	In multi-master mode:
	SSLA0 pin for input, and SSLA1 to	SSLA0 pin for input, and SSLA1 to
	SSLA3 pins for either output or	SSLA3 pins for either output or
	unused.	unused.
	In slave mode:	• In slave mode:
	SSLA0 pin for input, and SSLA1 to SSLA3 pins for unused.	SSLA0 pin for input, and SSLA1 to SSLA3 pins for unused.
	Controllable delay from SSL	Controllable delay from SSL
	output assertion to RSPCK	output assertion to RSPCK
	operation (RSPCK delay)	operation (RSPCK delay)
	 Range: 1 to 8 RSPCK cycles 	— Range: 1 to 8 RSPCK cycles
	(set in RSPCK-cycle units)	(set in RSPCK-cycle units)
	Controllable delay from RSPCK	Controllable delay from RSPCK
	stop to SSL output negation	stop to SSL output negation
	(SSL negation delay)	(SSL negation delay)
	 Range: 1 to 8 RSPCK cycles (set in RSPCK-cycle units) 	— Range: 1 to 8 RSPCK cycles (set in RSPCK-cycle units)
	Controllable wait for next-access	Controllable wait for next-access
	SSL output assertion (next-access delay)	SSL output assertion (next- access delay)
	— Range:1 to 8 RSPCK cycles	— Range:1 to 8 RSPCK cycles
	(set in RSPCK-cycle units)	(set in RSPCK-cycle units)
	Function for changing SSL	Function for changing SSL
	polarity	polarity
Control in master	A transfer of up to eight	A transfer of up to eight
transfer	commands can be executed	commands can be executed
	sequentially in looped execution.	sequentially in looped execution.
	 For each command, the following can be set: 	 For each command, the following can be set:
	SSL signal value, bit rate, RSPCK	SSL signal value, bit rate, RSPCK
	polarity/phase, transfer data length,	polarity/phase, transfer data length,
	MSB/LSB first, burst, RSPCK delay,	MSB/LSB first, burst, RSPCK delay,
	SSL negation delay, and next-access	SSL negation delay, and next-access delay
	delay	1
	 A transfer can be initiated by writing to the transmit buffer. 	 A transfer can be initiated by writing to the transmit buffer.
	 MOSI signal value specifiable in 	 MOSI signal value specifiable in
	SSL negation	SSL negation
		RSPCK auto-stop function
	I	TOT STAULO GLOP IGNOLIGIT

Item	RX111 (RSPI)	RX140 (RSPIc)
Interrupt sources	 Receive buffer full interrupt Transmit buffer empty interrupt RSPI error interrupt (mode fault, overrun, or parity error) RSPI idle interrupt (RSPI idle) 	 Receive buffer full interrupt Transmit buffer empty interrupt Error interrupt (mode fault, overrun, underrun, or parity error) Idle interrupt
Other functions	 Function for switching between CMOS output and open-drain output Function for initializing the RSPI Loopback mode 	 Function for switching between CMOS output and open-drain output Function for initializing the RSPI Loopback mode
Low power consumption function	Ability to specify module stop state.	Ability to specify module stop state.

Table 2-51 Comparison of Serial Peripheral Interface Registers

Register	Bit	RX111 (RSPIa)	RX140 (RSPIc)
SPSR	MODF	Mode fault error flag	Mode fault error flag
		0: No mode fault error occurs	Neither a mode fault error nor an underrun error occurs
		1: A mode fault error occurs	A mode fault error or an underrun error occurs
	UDRF	_	Underrun error flag
SPDR	_	RSPI data register	RSPI data register
		Accessible size • Longwords access (SPDCR.SPLW = 1) • Words access (SPDCR.SPLW = 0)	Accessible size Longwords access (SPDCR.SPLW = 1, SPBYTE = 0) Words access (SPDCR.SPLW = 0, SPBYTE = 0) Bytes access (SPDCR.SPBYT = 1)
SPDCR	SPBYT	_	RSPI byte access specification bit
SPCR2	SPPE	Parity enable bit 0: A parity bit is not added to transmit data, and no parity checking of receive data is performed. 1: A parity bit is added to transmit data, and parity checking of receive data is performed (when SPCR.TXMD = 0). A parity bit is added to transmit data, but no parity checking of receive data is performed (when SPCR.TXMD = 1).	Parity enable bit 0: A parity bit is not added to transmit data, and no parity checking of receive data is performed. 1: A parity bit is added to transmit data, and parity checking of receive data is performed.
000000	SCKASE	_	RSPCK auto-stop function enable bit
SPDCR2		_	RSPI data control register 2

2.21 12-Bit A/D Converter

Table 2-52 is a comparative overview of the 12-bit A/D converters, and Table 2-53 is a comparison of 12-bit A/D converter registers, and Table 2-54 is a comparison of A/D conversion start triggers that can be set in the ADSTRGR registers.

Table 2-52 Comparative Overview of 12-Bit A/D Converters

Item	RX111 (S12ADb)	RX140 (S12ADE)
Number of units	1 unit	1 unit
Input channels	14 channels	18 channels
Extended analog	Temperature sensor output, internal	Temperature sensor output, internal
function	reference voltage	reference voltage
A/D conversion method	Successive approximation method	Successive approximation method
Resolution	12 bits	12 bits
Conversion time	1.0 µs per channel (when A/D conversion clock ADCLK = 32 MHz)	Per channel Conversion cycle bit = 0: 0.88 μs, conversion cycle bit = 1: 0.67 μs (when A/D conversion clock (ADCLK) = 48 MHz)
A/D conversion clock	Peripheral module clock PCLK and A/D conversion clock ADCLK can be set so that the frequency ratio should be one of the following. PCLK to ADCLK frequency ratio = 1:1, 1:2, 1:4, 1:8, 2:1, 4:1 ADCLK is set using the clock generation circuit.	Peripheral module clock PCLKB and A/D conversion clock ADCLK can be set so that the frequency ratio should be one of the following. PCLKB to ADCLK frequency ratio = 1:1, 1:2, 2:1, 4:1, 8:1 ADCLK is set using the clock generation circuit.
Data registers	 14 registers for analog input and one for A/D-converted data duplication in double trigger mode One register for temperature sensor output One register for internal reference The results of A/D conversion are stored in 12-bit A/D data registers. 	 18 registers for analog input, one for A/D-converted data duplication in double trigger mode One register for temperature sensor output One register for internal reference One register for self-diagnosis The results of A/D conversion are stored in 12-bit A/D data registers. 12-bit accuracy output for the results of A/D conversion

Item	RX111 (S12ADb)	RX140 (S12ADE)
Data registers	In addition mode, A/D conversion results are added and stored in A/D data registers as 14-bit data.	The value obtained by adding up A/D-converted results is stored as a value in the number of bit for conversion accuracy + 2 bits/4 bits in the A/D data registers in A/D-converted value addition mode.
	 Duplication of A/D conversion data A/D conversion data of one selected analog input channel is stored in A/D data register y when conversion is started by the first trigger and into the duplication register when started by the second trigger. Duplication is available only in single scan mode or group scan mode when double trigger mode is selected. 	Double trigger mode (selectable in single scan and group scan modes): The first piece of A/D-converted analog-input data on one selected channel is stored in the data register for the channel, and the second piece is stored in the duplication register.
Operating mode	 Single scan mode: A/D conversion is performed only once on the analog inputs of up to 14 channels arbitrarily selected. A/D conversion is performed only once on the temperature sensor output. A/D conversion is performed only once on the internal reference voltage. Continuous scan mode: A/D conversion is performed repeatedly on the analog inputs of up to 14 channels arbitrarily selected. Group scan mode: Analog inputs of up to 14 channels are divided into group A and group B, and A/D conversion of the analog inputs selected on a group basis is performed only once. Conversion start conditions (synchronous trigger) can be selected independently for group A and group B, allowing A/D conversion of the groups to start at different times. 	 Single scan mode: A/D conversion is performed only once on the analog inputs of up to 18 channels arbitrarily selected. A/D conversion is performed only once on the temperature sensor output. A/D conversion is performed only once on the internal reference voltage. Continuous scan mode: A/D conversion is performed repeatedly on the analog inputs of up to 18 channels arbitrarily selected. Group scan mode: Analog inputs of up to 18 arbitrarily selected channels are divided into group A and group B, and A/D conversion of the analog inputs selected on a group basis is performed only once. Conversion start conditions (synchronous trigger) can be selected independently for group A and group B, allowing A/D conversion of the groups to start at different times.

Item	RX111 (S12ADb)	RX140 (S12ADE)
Operating mode		 Group scan mode (when group A is given priority): If a group A trigger is input during A/D conversion on group B, A/D conversion on group B is stopped and A/D conversion is performed on group A. Restart (rescan) of A/D conversion on group B after completion of A/D conversion on group A can be enabled.
Conditions for A/D conversion start	 Software trigger Synchronous trigger Trigger by MTU or ELC Asynchronous trigger A/D conversion can be triggered by the ADTRG0# pin. 	 Software trigger Synchronous trigger Trigger by the multi-function timer pulse unit (MTU) or event link controller (ELC) Asynchronous trigger A/D conversion can be triggered by the external trigger ADTRG0# pin.
Functions	 Variable sampling state count A/D-converted value addition mode Double trigger mode (duplication of A/D conversion data) 	 Variable sampling state count Self-diagnosis of 12-bit A/D converter Selectable A/D-converted value addition mode or average mode Analog input disconnection detection function (discharge function/precharge function) Double trigger mode (duplication of A/D conversion data) Automatic clear function of A/D data registers Compare function (window A and window B) 16 ring buffers when the compare function is used

Item	RX111 (S12ADb)	RX140 (S12ADE)
Interrupt sources	 In the modes except double trigger mode and group scan mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of single scan. In double trigger mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of double scan. In group scan mode, an A/D scan end interrupt request (S12ADI0) can be generated on completion of group A scan, whereas an A/D scan end interrupt request (GBADI) for group B can be generated on completion of group B scan. When double trigger mode is selected in group scan mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of double scan of group A, whereas A/D scan end interrupt request (GBADI) specially for group B can be generated on completion of group B scan. The S12ADI and GBADI interrupts can activate the data transfer controller (DTC). 	 In the modes except double trigger mode and group scan mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of single scan. In double trigger mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of double scan. In group scan mode, an A/D scan end interrupt request (S12ADI0) can be generated on completion of group A scan, whereas an A/D scan end interrupt request (GBADI) for group B can be generated on completion of group B scan. When double trigger mode is selected in group scan mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of double scan of group A, whereas A/D scan end interrupt request (GBADI) specially for group B can be generated on completion of group B scan. The S12ADI0 and GBADI interrupts can activate the data transfer controller (DTC).
Event link function	 An ELC event can be generated on completion of scans except for group B scan in group scan mode. A/D conversion can be started by the trigger from ELC. 	 An ELC event is generated on completion of scans other than group B scan in group scan mode. An ELC event is generated on completion of group B scan in group scan mode. An ELC event is generated on completion of all scans. Scan can be started by a trigger output by the ELC. An ELC event is generated according to the event conditions of the window compare function in single scan mode.
Reference voltage	 VREFH0, AVCC0, or the internal reference voltage can be selected as the high-side reference voltage by PJ6PFS.ASEL. VREFL0 or AVSS0 can be selected as the low-side reference voltage by PJ7PFS.ASEL. . 	 The external pin input (VREFH0) or the analog reference voltage (AVCC0) is selectable as the reference voltage on the high-potential side by HVSEL[1:0]. The external pin input (VREFL0) or the analog reference voltage (AVSS0) is selectable as the reference voltage on the low-potential side by LVSEL.

Item	RX111 (S12ADb)	RX140 (S12ADE)
Low power	Ability to specify module stop state	Ability to specify module stop state
consumption		
function		

Table 2-53 Comparison of 12-Bit A/D Converter Registers

Register	Bit	RX111 (S12ADb)	RX140 (S12ADE)
ADDRy	_	A/D data register y	A/D data register y
		(y = 0 to 4, 6, 8 to 15)	(y = 0 to 8, 16 to 21, 24 to 26)
ADRD	_	—	A/D self-diagnosis data register
ADANSA	_	AD channel select register A	_
ADANSA0	_	_	AD channel select register A0
ADANSA1	_	_	AD channel select register A1
ADANSB	_	AD channel select register B	_
ADANSB0	_	—	AD channel select register B0
ADANSB1	_	—	AD channel select register B1
ADADS	_	A/D-converted value addition mode select register	_
ADADS0	_	_	A/D-converted value addition/ average channel select register 0
ADADS1	_	_	A/D-converted value addition/ average channel select register 1
ADADC	ADC[1:0] (RX111) ADC[2:0]	Addition count select bits (b1, b0)	Addition count select bits (b2 to b0)
	(RX140)	b1 b0 0 0: 1-time conversion	b2 b0 0 0 0: 1-time conversion
ADOED	AVEE	 -	Average mode enable bit
ADCER	DIAGVAL[1:0]	_	Self-diagnosis conversion voltage select bits
	DIAGLD		Self-diagnosis mode select bit
	DIAGED		Self-diagnosis enable bit
ADSTRGR	TRSB[3:0] (RX111) TRSB[5:0] (RX140)	A/D conversion start trigger select bits for group B (b0 to b3) 0001 : TRG0AN 0010 : TRG0BN 0011 : TRGAN 0100 : TRG0EN 0101 : TRG0FN 0101 : TRG4AN 0110 : TRG4AN 0111 : TRG4BN 1000 : TRG4ABN 1001 : ELC	A/D conversion start trigger select bits for group B (b0 to b5) 00 0001 : TRG0AN 00 0010 : TRG0BN 00 0011 : TRG0EN 00 0100 : TRG0EN 00 0101 : TRG0FN 00 0110 : TRG4AN 00 0111 : TRG4BN 00 1000 : TRG4BN 01 1111 : TRG4BN 01 1001 : ELCTRG0 11 1111 : Trigger source deselection state

Register	Bit	RX111 (S12ADb)	RX140 (S12ADE)
	TRSA[3:0]	A/D conversion start trigger	A/D conversion start trigger
	(RX111)	select bits (b8 to b11)	select bits (b8 to b13)
	TRSA[5:0]	0001 : TRG0AN	00 0001 : TRG0AN
	(RX140)	0010 : TRG0BN	00 0010 : TRG0BN
		0011 : TRGAN	00 0011 : TRGAN
		0100 : TRG0EN	00 0100 : TRG0EN
		0101 : TRG0FN	00 0101 : TRG0FN
		0110 : TRG4AN	00 0110 : TRG4AN
		0111 : TRG4BN	00 0111 : TRG4BN
		1000 : TRG4ABN	00 1000 : TRG4ABN
		1001 : ELC	00 1001 : ELCTRG0
			11 1111 : Trigger source
			deselection state
ADEXICR	TSS(RX111)	Temperature Sensor Output	Temperature Sensor Output A/D
	TSSA(RX140)	A/D Conversion Select	Conversion Select
	OCS(RX111)	Internal Reference Voltage	Internal Reference Voltage A/D
	OCSA(RX140)	A/D Conversion Select	Conversion Select
ADSSTRn	000A(11X140)	A/D sampling state register n	A/D sampling state register n
ADSSTRII	_	(n = 0 to 4, 6, L, T, O)	(n = 0 to 8, L, T, O)
ADDISCR	_	_	A/D disconnection detection
			control register
ADELCCR	_	_	A/D event link control register
ADGSPCR	_	_	A/D group scan priority control
			register
ADCMPCR	_	_	A/D compare function control
			register
ADCMPANSR0	_	_	A/D compare function window A
			channel select register 0
ADCMPANSR1	_	_	A/D compare function window A
			channel select register 1
ADCMPANSER	_	_	A/D compare function window A
			extended input select register
ADCMPLR0	_	_	A/D compare function window A
			comparison condition setting
450145154			register 0
ADCMPLR1	_	_	A/D compare function window A
			comparison condition setting
ADOMDI ED			register 1
ADCMPLER		_	A/D compare function window A
			extended input comparison
ADOMODDO			condition setting register
ADCMPDR0	_	_	A/D compare function window A
ADCMPDR1			lower-side level setting register A/D compare function window A
ADCIVIFURI		_	upper-side level setting register
ADCMDODA			
ADCMPSR0	_		A/D compare function window A
ADCMPSR1			channel status register 0
ADCIVIPSKI		_	A/D compare function window A channel status register 1
ADCMPSER			A/D compare function window A
ADOME SEK	_		extended input channel status
			register
		1	rogistor

Register	Bit	RX111 (S12ADb)	RX140 (S12ADE)
ADHVREFCNT	_	_	A/D high-potential/low-potential
			reference voltage control register
ADWINMON		_	A/D compare function window
			A/B status monitor register
ADCMPBNSR		_	A/D compare function window B
			channel select register
ADWINLLB		_	A/D compare function window B
			lower-side level setting register
ADWINULB		_	A/D compare function window B
			upper-side level setting register
ADCMPBSR		_	A/D compare function window B
			channel status register
ADBUFn		_	A/D data storage buffer register n
			(n = 0 to 15)
ADBUFEN	_	_	A/D data storage buffer enable
			register
ADBUFPTR		_	A/D data storage buffer pointer
			register
ADCCR	_	_	A/D conversion cycle control
			register

Table 2-54 Comparison of A/D Conversion Start Triggers Set in the ADSTRGR Registers

Bit	RX111 (S12ADb)	RX140 (S12ADE)
TRSB[3:0]	A/D conversion start trigger select for group	A/D conversion start trigger select for group
(RX111)	B bits	B bits
TRSB[5:0]		
(RX140)	b3 b0	b5 b0
		1 1 1 1 1: No trigger source selected state
	0 0 0 1: TRG0AN	0 0 0 0 0 1: TRG0AN
	0 0 1 0: TRG0BN	0 0 0 0 1 0: TRG0BN
	0 0 1 1: TRGAN	0 0 0 0 1 1: TRGAN
	0 1 0 0: TRG0EN	0 0 0 1 0 0: TRG0EN
	0 1 0 1: TRG0FN	0 0 0 1 0 1: TRG0FN
		0 0 0 1 1 0: TRG4AN
		0 0 1 1 1 1: TRG4BN
		0 0 1 0 0 0: TRG4ABN
		0 0 1 0 0 1: ELCTRG0
TRSA[3:0] (RX111)	A/D conversion start trigger select bits	A/D conversion start trigger select bits
TRSA[5:0]	b11 b8	b13 b8
(RX140)		1 1 1 1 1 1: No trigger source selected state
	0 0 0 0: ADTRG0#	0 0 0 0 0 0: ADTRG0#
	0 0 0 1: TRG0AN	0 0 0 0 0 1: TRG0AN
	0 0 1 0: TRG0BN	0 0 0 0 1 0: TRG0BN
	0 0 1 1: TRGAN	000011: TRGAN
	0 1 0 0: TRG0EN	0 0 0 1 0 0: TRG0EN
	0 1 0 1: TRG0FN	0 0 0 1 0 1: TRG0FN
		0 0 0 1 1 0: TRG4AN
		0 0 0 1 1 1: TRG4BN
		0 0 1 0 0 0: TRG4ABN
		0 0 1 0 0 1: ELCTRG0

2.22 D/A Converter

Table 2-55 is a comparative overview of the D/A converter, and Table 2-56 is a comparison of D/A converter registers.

Table 2-55 Comparative Overview of D/A converter

Item	RX111(DA)	RX140(DAa)
Resolution	8 bits	8 bits
Output channels	Two channels	Two channels
Low power consumption function	Module stop state can be set for each unit.	Module stop state can be set.
Event link function (input)	DA0 conversion can be started when an event signal is input.	DA0 conversion can be started when an event signal is input.
Measure against mutual interference between analog modules		Measure against interference between D/A and A/D conversion D/A converted data update timing is controlled by the 12-bit A/D converter synchronous D/A conversion enable signal from the 12-bit A/D converter. Therefore, the degradation of A/D conversion accuracy due to interference is reduced by controlling the timing in which the 8-bit D/A converter inrush current occurs, with the enable signal.
Pin Configuration	VCC Input Power supply pin	AVCC0 Input Analog voltage supply pin for the 12-bit A/D converter and 8-bit D/A converter. Connect this pin to VCC when not using the 12-bit A/D converter and 8-bit D/A converter.
	VSS Input Ground pin	AVSS0 Input Analog ground pin for the 12-bit A/D converter and 8-bit D/A converter. Connect this pin to VSS when not using the 12-bit A/D converter and 8-bit D/A converter.
	DA0 Output Channel 0 analog output pin	DA0 Output Channel 0 analog output pin
	DA1 Output Channel 1 analog output pin	DA1 Output Channel 1 analog output pin

Table 2-56 Comparison of D/A converter Registers

Register	Bit	RX111(DA)	RX140(DAa)
DACR	DAOE0	0: Analog output of channel 0 (DA0) is disabled.	0: Analog output of channel 0 (DA0) is disabled.
		1: D/A conversion of channel 0 is enabled.	1: D/A conversion of channel 0 is enabled.
		Analog output of channel 0 (DA0) is enabled.*1	Analog output of channel 0 (DA0) is enabled.
	DAOE1	0: Analog output of channel 1 (DA1) is disabled.	0: Analog output of channel 1 (DA1) is disabled.
		1: D/A conversion of channel 1 is enabled.	1: D/A conversion of channel 1 is enabled.
		Analog output of channel 1 (DA1) is enabled.*1	Analog output of channel 1 (DA1) is enabled.
DAADSCR	_	_	D/A A/D Synchronous Start Control Register

Note 1. Set the P0.PDR.Bm bit (m = 3, 5) for pins used as analog outputs and the corresponding P0.PMR.Bm bit (m = 3, 5) to 0. In addition, set them to analog pins by the P03PFS and P05PFS registers. For details, refer to section 18, I/O Ports and section 19, Multi-Function Pin Controller (MPC).

2.23 Temperature Sensor

Table 2-57 is a comparison of temperature sensor registers.

Table 2-57 Comparison of Temperature Sensor Registers

Register	Bit	RX111 (TEMPSA)	RX140 (TEMPSA)
TSCDRH,	_	Temperature sensor calibration	Temperature sensor calibration
TSCDRL (RX111)		data register	data register
TSCDR (RX140)			

2.24 RAM

Table 2.58 is a comparative overview of RAM.

Table 2-58 Comparative Overview of RAM

Item	RX111	RX140
RAM capacity	Max. 64 KB	Max. 64 KB
RAM address	RAM capacity 64 KB RAM0: 0000 0000h to 0000 FFFFh	 RAM capacity 64 KB RAM0: 0000 0000h to 0000 FFFFh
	 RAM capacity 32 KB RAM0: 0000 0000h to 0000 7FFFh 	 RAM capacity 32 KB RAM0: 0000 0000h to 0000 7FFFh
	 RAM capacity 16 KB RAM0: 0000 0000h to 0000 3FFFh 	 RAM capacity 16 KB RAM0: 0000 0000h to 0000 3FFFh
	 RAM capacity 10 KB RAM0: 0000 0000h to 0000 27FFh 	
	 RAM capacity 8 KB RAM0: 0000 0000h to 0000 1FFFh 	
Access	 Single-cycle access is possible for both reading and writing. 	 Single-cycle access is possible for both reading and writing.
	 RAM can be enabled or disabled. 	 RAM can be enabled or disabled.
Low power consumption function	Ability to specify module stop state	Ability to specify module stop state

2.25 Flash Memory

Table 2.59 is a comparative overview of flash memory, and Table 2.60 is a comparison of flash memory registers.

Table 2-59 Comparative Overview of Flash Memory

Item	RX111	RX140 (FLASH)
Memory capacity	 User area: Up to 512 KB Data area: 8 KB Extra area: Stores the start-up area information, access window information, and unique ID 	 User area: Up to 256 KB Data area: Up to 8 KB Extra area: Stores the start-up area information, access window information, and unique ID
Operating clock		 FCLK: 1 to 48 MHz (for ROM P/E mode and E2 DataFlash P/E mode) up to 48 MHz (for E2 DataFlash read mode) HOCO clock: 24 MHz, 32 MHz, or 48 MHz (for ROM P/E mode and E2 DataFlash P/E mode)
Software commands	 The following software commands are implemented: Program, blank check, block erase, and unique ID read The following commands are implemented for programming the extra area: Start-up area information program and access window information program 	 The following software commands are implemented: Program, blank check, block erase, and all-block erase The following commands are implemented for programming the extra area: Start-up area information program, access window protect, and access window information program
Value after	ROM: FFh	ROM: FFh
erasure	E2 DataFlash: FFh	E2 DataFlash: FFh
Interrupt	An interrupt (FRDYI) is generated upon completion of software command processing or forced stop processing.	An interrupt (FRDYI) is generated upon completion of software command processing or forced stop processing.

Item	RX111	RX140 (FLASH)
On-board programming	 Boot mode (SCI interface) Channel 1 of the serial communications interface (SCI1) is used for asynchronous communication. The user area and data area are rewritable. Boot mode (FINE interface) The FINE interface is used. The user area and data area are rewritable. Boot mode (USB interface) Channel 0 of the USB 2.0 function (USB0) module is used. The user area and data area are rewritable. The flash memory can be rewritable in self-powered or bus-powered mode. A personal computer can be connected using only a USB cable. Self-programming (single-chip mode) The user area can be programmed using a flash programming routine in a user program. 	Boot mode (SCI interface) Channel 1 of the serial communications interface (SCI1) is used for asynchronous communication. The user area and data area can be programmed. Boot mode (FINE interface) The FINE interface is used. The user area and data area can be programmed. Self-programming (single-chip mode) The user area and data area can be programmed using a flash programming routine in a user program.
Off-board programming	The user area and data area are rewritable using a flash programmer compatible with this MCU.	The user area and data area can be programmed using a flash programmer compatible with the MCU.
ID code protection	Connection with a serial programmer can be controlled using ID codes in boot mode. Connection with an on-chip debugging emulator can be controlled using ID codes.	Connection with a serial programmer can be controlled using ID codes in boot mode. Connection with an on-chip debugging emulator can be controlled using ID codes.
Start-up program protection function	This function is used to safely program blocks 0 to 15.	This function is used to safely program blocks 0 to 7.
Area protection	During self-programming, this function enables programming only of specified blocks in the user area and disables programming of the other blocks.	During self-programming, this function enables programming only of specified blocks in the user area and disables programming of the other blocks.
Background operation (BGO) function	Programs on the ROM can be executed while rewriting the E2 DataFlash.	Programs in the ROM can run while the E2 DataFlash is being programmed.

Item	RX111	RX140 (FLASH)
Addresses	 Products with capacity of 512 KB FFF8 0000h to FFFF FFFFh 	
	 Products with capacity of 384 KB FFFA 0000h to FFFF FFFFh 	
	 Products with capacity of 256 KB FFFC 0000h to FFFF FFFFh 	 Products with capacity of 256 KB FFFC 0000h to FFFF FFFFh
	 Products with capacity of 128 KB FFFE 0000h to FFFF FFFFh 	 Products with capacity of 128 KB FFFE 0000h to FFFF FFFFh
	 Products with capacity of 96 KB FFFE 8000h to FFFF FFFFh 	
	 Products with capacity of 64 KB FFFF 0000h to FFFF FFFFh 	 Products with capacity of 64 KB FFFF 0000h to FFFF FFFFh
	 Products with capacity of 32 KB FFFF 8000h to FFFF FFFFh 	
E2 DataFlash	Products with capacity of 8 KB 0010 0000h to 0010 1FFFh	 Products with capacity of 8 KB 0010 0000h to 0010 1FFFh
		 Products with capacity of 4 KB 0010 0000h to 0010 0FFFh

Table 2-60 Comparison of Flash Memory Registers

Register	Bit	RX111	RX140 (FLASH)
MEMWAITR		_	Memory wait cycle setting register
DFLWAITR			Data flash wait cycle setting register
FPMCR	FMS0, FMS1, FSM2 (RX111)	Flash operating mode select bits 0, 1, and 2	Flash operating mode select bits 0 and 1
	FMS0, FMS1	FMS2 FMS1 FMS0	FMS1 FMS0
	(RX140)	0 0 0: ROM/E2 DataFlash read mode	0 0: ROM/E2 DataFlash read mode
			0 1: ROMP/E mode
		0 1 0: E2 DataFlash P/E mode	1 0: E2 DataFlash P/E mode
		0 1 1: Discharge mode 1	1 1: Setting prohibited
		1 0 1: ROM P/E mode	
		1 1 1: Discharge mode 2	
		Settings other than the above are prohibited.	
	LVPE	Low-voltage P/E mode enable bit	
FICE		5	Devinte and alcohomatification bits
FISR	PCKA[4:0] (RX111) PCKA[5:0] (RX140)	Peripheral clock notification bits	Peripheral clock notification bits
FCR	CMD[3:0]	Software command setting bits	Software command setting bits
		b3 b0	b3 b0
		0 0 0 1: Program	0 0 0 1: Program
		0 0 1 1: Blank check	0 0 1 1: Blank check
		0 1 0 0: Block erase	0 1 0 0: Block erase
		0 1 0 1: Unique ID read	
		·	0 1 1 0: All-block erase
		Settings other than the above are prohibited.	Settings other than the above are prohibited.

Register	Bit	RX111	RX140 (FLASH)	
	DRC	Data read completion bit	_	
FEXCR	CMD[2:0]	Software command setting bits	Software command setting bits	
		b2 b0	b2 b0	
		0 0 1: Start-up area information program	0 0 1: Start-up area information program/access window protect	
		0 1 0: Access window information program	0 1 0: Access window information program	
		Settings other than the above are prohibited.	Settings other than the above are prohibited.	
FSARH	_	Flash processing start address register H	Flash processing start address register H	
		FSARH is an 8-bit register.	FSARH is a 16-bit register.	
FEARH	_	Flash processing end address	Flash processing end address	
		register H	register H	
		FEARH is an 8-bit register.	FEARH is a 16-bit register.	
FRBH	_	Flash read buffer register H	_	
FRBL	_	Flash read buffer register L	_	
FWBH, FWBL (RX111)	_	Flash write buffer register H, Flash write buffer register L	Flash write buffer register n (n = 0 to 3)	
FWBn (RX140)				
FSTATR1	DRRDY	Data read ready flag	-	
FEAMH		Flash error address monitor register H	Flash error address monitor register H	
		FEAMH is an 8-bit register.	FEAMH is a 16-bit register.	
FSCMR	AWPR	_	Access window protect flag	
FAWSMR —		Flash Access Window Start Address Monitor Register	Flash Access Window Start Address Monitor Register	
		Initial value after a reset differs	-	
		Flash Access Window End Address Monitor Register	Flash Access Window End Address Monitor Register	
		Initial value after a reset differs	·	
UIDRn	_	Unique ID register n (n = 0 to 31)	Unique ID register n (n = 0 to 3)	
		UIDRn is an 8-bit register.	UIDRn is a 32-bit register.	

2.26 Packages

As indicated in Table 2.61, there are discrepancies in the package drawing codes and availability of some package types, and this should be borne in mind at the board design stage. For details, refer to Design Guide for Migration between RX Family: Differences in Package External form (R01AN4591EJ).

Table 2-61 Packages

	Renesas Code		
Package Type	RX111	RX140	
80-pin LFQFP	×	0	
64-pin LFQFP	PLQP0064KB-A	PLQP0064KB-C	
64-pin WFLGA	0	×	
48-pin LFQFP	PLQP0048KB-A	PLQP0048KB-B	
48-pin HWQFN	PWQN0048KB-A	PWQN0048KC-A	
40-pin HWQFN	0	×	
36-pin WFLGA	0	×	
32-pin LQFP	×	0	
32-pin HWQFN	×	0	

O: Package available (Renesas code omitted); X: Package not available

3. Comparison of Pin Functions

This section presents a comparative description of pin functions as well as a comparison of the pins for the power supply, clocks, and system control. Items that exist only on one group are indicated by **blue text**. Items that exists on both groups with different specifications are indicated by **red text**. **Black text** indicates there is no differences in the item's specifications between groups.

3.1 64-Pin Package

Table 3.1 is a comparative listing of the pin functions of 64-pin package products.

Table 3-1 Comparative Listing of 64-Pin Package Pin Functions

64-Pin LFQFP/		
LQFP	RX111	RX140
1	P03/DA0	P03*1/DA0
2	P27/MTIOC2B/SCK1/SCK12/IRQ3/CMPA2/ CACREF/ADTRG0#	VCL
3	P26/MTIOC2A/TXD1/SMOSI1/SSDA1/ USB0_VBUSEN	MD/PG7/FINED
4	P30/RXD1/SMISO1/SSCL1/IRQ0/ MTIOC4B/POE8#	XCIN/PH7*3
5	P31/CTS1#/RTS1#/SS1#/IRQ1/MTIOC4D	XCOUT/PH6*3
6	MD/FINED	RES#
7	RES#	XTAL/P37/IRQ4
8	XCOUT	VSS
9	XCIN	EXTAL/P36/IRQ2
10	P35/NMI/USEL	VCC
11	XTAL	P35/NMI
12	EXTAL	P32/MTIOC0C/TMO3/TXD6*3/SMOSI6*3/ SSDA6*3/TS0*3/IRQ2/RTCOUT
13	VCL	P31/MTIOC4D/TMCI2/CTS1#/RTS1#/SS1#/ TS1*3/IRQ1
14	VSS	P30/MTIOC4B/TMRI3/POE8#/RXD1/ SMISO1/SSCL1/TS2*3/IRQ0
15	VCC	P27/MTIOC2B/TMCI3/SCK1/TS3
16	P32/MTIOC0C/RTCOUT/IRQ2	P26/MTIOC2A/TMO1/LPTO/TXD1/SMOSI1/ SSDA1/TS4
17	P17/MTIOC3A/MTIOC3B/MTIOC0C/ POE8#/SCK1/MISOA/SDA0/RXD12/ RXDX12/SMISO12/SSCL12/IRQ7	P17/MTIOC3A/MTIOC3B/TMO1/POE8#/ SCK1/MISOA/SDA0/IRQ7
18	P16/MTIOC3C/MTIOC3D/RTCOUT/ TXD1/SMOSI1/SSDA1/MOSIA/SCL0/ IRQ6/ADTRG0#/USB0_VBUS/ USB0_VBUSEN/USB0_OVRCURB	P16/MTIOC3C/MTIOC3D/TMO2/TXD1/ SMOSI1/SSDA1/MOSIA/SCL0/IRQ6/ RTCOUT/ADTRG0#
19	P15/MTIOC0B/MTCLKB/RXD1/SMISO1/ SSCL1/RSPCKA/IRQ5/CLKOUT	P15/MTIOC0B/MTCLKB/TMCI2/RXD1/ SMISO1/SSCL1/CRXD0/TS5*3/IRQ5
20	P14/MTIOC3A/MTIOC0A/MTCLKA/CTS1#/ RTS1#/SS1#/SSLA0/TXD12/TXDX12/ SIOX12/SMOSI12/SSDA12/IRQ4/UB#/ USB0_OVRCURA	P14/MTIOC3A/MTCLKA/TMRI2/CTS1#/ RTS1#/SS1#/CTXD0/TS6*3/IRQ4
21	VCC_USB	PH3/MTIOC4D/TMCI0/TS7*3
22	USB0_DM	PH2/MTIOC4C/TMRI0/TS8*3/IRQ1

64-Pin		
LFQFP/		
LQFP	RX111	RX140
23	USB0_DP	PH1/MTIOC3D/TMO0/TS9*3/IRQ0
24	VSS_USB	PH0/MTIOC3B/TS10*3/CACREF
25	P55/MTIOC4D	P55/MTIOC4A/MTIOC4D/TMO3/CRXD0/
		TS11* ³
26	P54/MTIOC4B	P54/MTIOC4B/TMCI1/CTXD0/TS12*3
27	PC7/MTIOC3A/MTCLKB/TXD1/SMOSI1/	PC7/MTIOC3A/MTCLKB/TMO2/LPTO/
	SSDA1/MISOA/CACREF/USB0_OVRCURB	TXD8*3/SMOSI8*3/SSDA8*3/MISOA/TS13/
		CACREF
28	PC6/MTIOC3C/MTCLKA/RXD1/SMISO1/	PC6/MTIOC3C/MTCLKA/TMCI2/RXD8*3/
	SSCL1/MOSIA/USB0_EXICEN	SMISO8*3/SSCL8*3/MOSIA/TS14
29	PC5/MTIOC3B/MTCLKD/SCK1/RSPCKA/	PC5/MTIOC0C/MTIOC3B/MTCLKD/TMRI2/ SCK8*3/RSPCKA/TS15
00	USB0_ID	
30	PC4/MTCLKC/SCK5/SSLA0/IRQ2/CLKOUT/	PC4/MTIOC0A/MTIOC3D/MTCLKC/TMCI1/ POE0#/SCK5/CTS8#*3/RTS8#*3/SS8#*3/
	USB0_VBUS/USB0_VBUSEN	SSLAO/TSCAP
31	PC3/MTIOC4D/TXD5/SMOSI5/SSDA5	PC3/MTIOC4D/TXD5/SMOSI5/SSDA5/
31	F C3/WITIOC4D/TXD3/3WIC3I3/33DA3	TS16*3
32	PC2/RXD5/SMISO5/SSCL5/SSLA3/	PC2/MTIOC4B/RXD5/SMISO5/SSCL5/
02	MTIOC4B	SSLA3/TS17*3
33	PB7/PC1/MTIOC3B	PB7/PC1*2/MTIOC3B/TXD9*3/SMOSI9*3/
	. 27/1 6 //	SSDA9*3/TS18*3
34	PB6/PC0/MTIOC3D	PB6/PC0*2/MTIOC3D/RXD9*3/SMISO9*3/
		SSCL9*3/TS19*3
35	PB5/MTIOC2A/MTIOC1B/POE1#	PB5/MTIOC2A/MTIOC1B/TMRI1/POE1#/
		SCK9*3/TS20*3
36	PB3/MTIOC0A/MTIOC3B/MTIOC4A/	PB3/MTIOC0A/MTIOC4A/TMO0/POE3#/
	POE3#/USB0_OVRCURA	LPTO/SCK6*3/TS22*3
37	PB1/MTIOC0C/IRQ4/MTIOC4C	PB1/MTIOC0C/MTIOC4C/TMCI0/TXD6*3/
		SMOSI6*3/SSDA6*3/TS24*3/IRQ4/CMPOB1
38	VCC	VCC
39	PB0/MTIC5W/MTIOC0C/RTCOUT/	PB0/MTIOC3D/MTIC5W/RXD6*3/SMISO6*3/
	SCL0/RSPCKA/IRQ2/ADTRG0#	SSCL6*3/RSPCKA/TS25
40	VSS	VSS
41	PA6/MTIC5V/MTCLKB/MTIOC2A/	PA6/MTIOC3D/MTIC5V/MTCLKB/TMCI3/
	CTS5#/RTS5#/SS5#/SDA0/MOSIA/IRQ3/	POE2#/CTS5#/RTS5#/SS5#/MOSIA/TS26*3
40	POE2#	DA 4/8 ATIO C 40/8 ATIO CILIBATOLIKA /TRADIO/
42	PA4/MTIC5U/MTCLKA/MTIOC2B/ TXD5/SMOSI5/SSDA5/SSLA0/IRQ5	PA4/MTIOC4C/MTIC5U/MTCLKA/TMRI0/ TXD5/SMOSI5/SSDA5/SSLA0/TS28/IRQ5/
	TAD5/5WO5I5/55DA5/55LAU/IRQ5	CVREFB1
43	PA3/MTIOC0D/MTCLKD/MTIOC1B/	PA3/MTIOC0D/MTIOC4D/MTIC5V/MTCLKD/
70	RXD5/SMISO5/SSCL5/MISOA/IRQ6/	RXD5/SMISO5/SSCL5/TS29/IRQ6/CMPB1
	POE0#	TO SO
44	PA1/MTIOC0B/MTCLKC/RTCOUT/	PA1/MTIOC0B/MTIOC3B/MTCLKC/SCK5/
' '	SCK5/SSLA2	SSLA2/TS31
45	PA0/MTIOC4A/SSLA1/CACREF	PA0/MTIOC4A/SSLA1/TS32*3/CACREF
46	PE5/MTIOC4C/MTIOC2B/IRQ5/AN013	PE5/MTIOC4C/MTIOC2B/IRQ5/AN021/
.0	25,	CMPOB0
47	PE4/MTIOC4D/MTIOC1A/MTIOC3A/	PE4/MTIOC4D/MTIOC1A/MTIOC4A/TS33/
	MOSIA/IRQ4/AN012	AN020/CMPA2/CLKOUT
L	<u> </u>	1

64-Pin LFQFP/		
LPQFP	RX111	RX140
48	PE3/MTIOC0A/MTIOC1B/MTIOC4B/	PE3/MTIOC1B/MTIOC4B/POE8#/CTS12#/
	CTS12#/RTS12#/SS12#/RSPCKA/IRQ3/	RTS12#/SS12#/TS34/AN019/CLKOUT
	AN011	
49	PE2/MTIOC4A/RXD12/RXDX12/SMISO12/	PE2/MTIOC4A/RXD12/RXDX12/SMISO12/
	SSCL12/IRQ7/AN010	SSCL12/TS35/IRQ7/AN018/CVREFB0
50	PE1/MTIOC4C/TXD12/TXDX12/SIOX12/	PE1/MTIOC4C/TXD12/TXDX12/SIOX12/
	SMOSI12/SSDA12/IRQ1/AN009	SMOSI12/SSDA12/AN017/CMPB0
51	PE0/MTIOC2A/SCK12/IRQ0/AN008/POE3#	PE0/SCK12/AN016
52	PE7/IRQ7/AN015	P47*1/AN007
53	PE6/IRQ6/AN014	P46*1/AN006
54	P46*1/AN006	P45*1/AN005
55	P44*1/AN004	P44*1/AN004
56	P43*1/AN003	P43*1/AN003
57	P42*1/AN002	P42*1/AN002
58	P41*1/AN001	P41*1/AN001
59	VREFL0/PJ7*1	VREFL0/PJ7*1
60	P40*1/AN000	P40*1/AN000
61	VREFH0/PJ6*1	VREFH0/PJ6*1
62	AVSS0	AVCC0
63	AVCC0	P05*1/DA1
64	P05/DA1	AVSS0

Notes: 1. The power supply of the I/O buffer for these pins is AVCCO.

- 2. PC0 and PC1 are valid only when the port switching function is selected.
- 3. Not implemented on products with ROM capacity of 64 KB.

3.2 48-Pin Package

Table 3.2 is a comparative listing of the pin functions of 48-pin package products.

Table 3-2 Comparative Listing of 48-Pin Package Pin Functions

48-Pin LFQFP/		
HWQFN	RX111	RX140
1	P27/MTIOC2B/SCK1/SCK12/ IRQ3/CMPA2/CACREF/ADTRG0#	VCL
2	P26/MTIOC2A/TXD1/SMOSI1/SSDA1/ USB0_VBUSEN	MD/PG7/FINED
3	MD/FINED	RES#
4	RES#	XTAL/P37/IRQ4
5	XCOUT	VSS
6	XCIN	EXTAL/P36/IRQ2
7	P35/NMI/UPSEL	VCC
8	XTAL	P35/NMI
9	EXTAL	P31/MTIOC4D/TMCI2/CTS1#/RTS1#/SS1#/ TS1*3/IRQ1
10	VCL	P30/MTIOC4B/TMRI3/POE8#/RXD1/ SMISO1/SSCL1/TS2*3/IRQ0
11	VSS	P27/MTIOC2B/TMCI3/SCK1/TS3
12	VCC	P26/MTIOC2A/TMO1/LPTO/TXD1/SMOSI1/ SSDA1/TS4
13	P17/MTIOC3A/MTIOC3B/MTIOC0C/POE8#/ SCK1/MISOA/SDA0/RXD12/ RXDX12/SMISO12/SSCL12/IRQ7	P17/MTIOC3A/MTIOC3B/TMO1/POE8#/ SCK1/MISOA/SDA0/IRQ7
14	P16/MTIOC3C/MTIOC3D/RTCOUT/ TXD1/SMOSI1/SSDA1/MOSIA/SCL0/IRQ6/ ADTRG0#/USB0_VBUS/USB0_VBUSEN/ USB0_OVRCURB	P16/MTIOC3C/MTIOC3D/TMO2/TXD1/ SMOSI1/SSDA1/MOSIA/SCL0/IRQ6/ ADTRG0#/RTCOUT
15	P15/MTIOC0B/MTCLKB/ RXD1/SMISO1/SSCL1/RSPCKA/ IRQ5/CLKOUT	P15/MTIOC0B/MTCLKB/TMCI2/RXD1/ SMISO1/SSCL1/CRXD0/TS5*3/IRQ5
16	P14/MTIOC3A/MTIOC0A/MTCLKA/ CTS1#/RTS1#/SS1#/SSLA0/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12/IRQ4/ USB0_OVRCURA	P14/MTIOC3A/MTCLKA/TMRI2/CTS1#/ RTS1#/SS1#/CTXD0/TS6*3/IRQ4
17	VCC_USB	PH3/MTIOC4D/TMCI0/TS7*3
18	USB0_DP	PH2/MTIOC4C/TMRI0/TS8*3/IRQ1
19	VSS_USB	PH1/MTIOC3D/TMO0/TS9*3/IRQ0
20	PH0/MTIOC1B/CACREF	PH0/MTIOC3B/TS10*3/CACREF
21	PC7/MTIOC3A/MTCLKB/ TXD1/SMOSI1/SSDA1/MISOA/CACREF/ USB0_OVRCURB	PC7/MTIOC3A/TMO2/MTCLKB/LPTO/ TXD8*3/SMOSI8*3/SSDA8*3/MISOA/TS13/ CACREF
22	PC6/MTIOC3C/MTCLKA/ RXD1/SMISO1/SSCL1/MOSIA/ USB0_EXICEN	PC6/MTIOC3C/MTCLKA/TMCI2/RXD8*3/ SMISO8*3/SSCL8*3/MOSIA/TS14
23	PC5/MTIOC3B/MTCLKD/SCK1/RSPCKA/ USB0_ID	PC5/MTIOC0C/MTIOC3B/MTCLKD/TMRI2/ SCK8*3/RSPCKA/TS15

48-Pin LFQFP/			
HWQFN	RX111	RX140	
24	PC4/MTIOC3D/MTCLKC/SCK5/SSLA0/	PC4/MTIOC0A/MTIOC3D/MTCLKC/TMCI1/	
	IRQ2/POE0#/CLKOUT/	POE0#/SCK5/CTS8#*3/RTS8#*3/SS8#*3/ SSLA0/TSCAP	
	USB0_VBUS/USB0_VBUSEN		
25	PB5/PC3/MTIOC2A/MTIOC1B/POE1#	PB5/PC3*1/MTIOC2A/MTIOC1B/TMRI1/ POE1#/TS20*3	
26	PB3/PC2/MTIOC0A/MTIOC4A/POE3#/	PB3/PC2*1/MTIOC0A/MTIOC4A/TMO0/	
	USB0_OVRCURA	POE3#/LPTO/SCK6*3/TS22*3	
27	PB1/PC1/MTIOC0C/MTIOC4C/IRQ4	PB1/PC1*1/MTIOC0C/MTIOC4C/TMCI0/ TXD6*3/SMOSI6*3/SSDA6*3/TS24*3/IRQ4/ CMPOB1	
28	VCC	VCC	
29	PB0/PC0/MTIC5W/MTIOC0C/RTCOUT/ SCL0/RSPCKA/IRQ2/ADTRG0#	PB0/PC0*1/MTIOC3D/MTIC5W/RXD6*3/ SMISO6*3/SSCL6*3/RSPCKA/TS25	
20	VSS		
30	PA6/MTIC5V/MTCLKB/MTIOC2A/POE2#/	VSS PA6/MTIOC3D/MTIC5V/MTCLKB/TMCI3/	
31	CTS5#/RTS5#/SS5#/SDA0/MOSIA/IRQ3	POE2#/CTS5#/RTS5#/SS5#/MOSIA/TS26*3	
32	PA4/MTIC5U/MTCLKA/MTIOC2B/	PA4/MTIOC4C/MTIC5U/MTCLKA/TMRIO/	
52	TXD5/SMOSI5/SSDA5/SSLA0/IRQ5	TXD5/SMOSI5/SSDA5/SSLA0/TS28/IRQ5/	
		CVREFB1	
33	PA3/MTIOC0D/MTCLKD/MTIOC1B/	PA3/MTIOC0D/MTIOC4D/MTIC5V/MTCLKD/	
	RXD5/SMISO5/SSCL5/MISOA/IRQ6/POE0#	RXD5/SMISO5/SSCL5/TS29/IRQ6/CMPB1	
34	PA1/MTIOC0B/MTCLKC/RTCOUT/	PA1/MTIOC0B/MTIOC3B/MTCLKC/SCK5/	
	SCK5/SSLA2	SSLA2/TS31	
35	PE4/MTIOC4D/MTIOC1A/MOSIA/IRQ4/	PE4/MTIOC4D/MTIOC1A/MTIOC4A/TS33/	
	AN012/MTIOC3A	AN020/CMPA2/CLKOUT	
36	PE3/MTIOC0A/MTIOC4B/MTIOC1B/POE8#/	PE3/MTIOC1B/MTIOC4B/POE8#/CTS12#/	
	CTS12#/RTS12#/SS12#/RSPCKA/	RTS12#/TS34/AN019/CLKOUT	
07	IRQ3/AN011	DEO/NITIO O A A /DVD 4 O /DVD VA O /O O O I 4 O /	
37	PE2/MTIOC4A/RXD12/RXDX12/SMISO12/ SSCL12/ IRQ7/AN010	PE2/MTIOC4A/RXD12/RXDX12/SSCL12/ TS35/IRQ7/AN018/CVREFB0	
38	PE1/MTIOC4C/TXD12/TXDX12/SIOX12/	PE1/MTIOC4C/TXD12/TXDX12/SIOX12/	
	SMOSI12/SSDA12/IRQ1/AN009	SSDA12/AN017/CMPB0	
39	PE0/MTIOC2A/SCK12/IRQ0/AN008/POE3#	P47*2/AN007	
40	PE7/IRQ7/AN015	P46*2/AN006	
41	P46*2/AN006	P45*2/AN005	
42	P42*2/AN002	P42*2/AN002	
43	P41*2/AN001	P41*2/AN001	
44	VREFL0/PJ7*2	VREFL0/PJ7*2	
45	P40*2/AN000	P40*2/AN000	
46	VREFH0/PJ6*2	VREFH0/PJ6*2	
47	AVSS0	AVCC0	
48	O to PC3 are valid only when the port switching	AVSS0	

Notes: 1. PC0 to PC3 are valid only when the port switching function is selected.

- 2. The power supply of the I/O buffer for these pins is AVCC0.
- 3. Not implemented on products with ROM capacity of 64 KB.

4. Important Information when Migrating Between MCUs

This section presents important information on differences between the RX140 Group and the RX111 Group. 4.1, Notes on Functional Design, presents information regarding the software.

4.1 Notes on Functional Design

Some software that runs on the RX111 Group is compatible with the RX140 Group. Nevertheless, appropriate caution must be exercised due to differences in aspects such as operation timing and electrical characteristics.

Software-related considerations regarding function settings that differ between the RX140 Group and RX111 Group are as follows:

For differences between modules and functions, refer to 2, Comparative Overview of Specifications. For further information, refer to the User's Manual: Hardware of each MCU group, listed in 5, Reference Documents.

4.1.1 12-Bit AD Converter

The RX140 Group incorporates significant changes to the 12-bit A/D converter registers, compared to the RX111 Group. This results in a reduction in software compatibility.

4.1.2 Exception Vector Table

On the RX111 Group the vector table is assigned to a fixed address space, but on the RX140 Group the vector table address can be changed by specifying a value for the start address in the exception table register (EXTB).

4.1.3 Restrictions on Comparison Function

On the RX140 Group the comparison function of the 12-bit A/D converter has the following restrictions:

- Use of the self-diagnostic function and double-trigger mode are prohibited.
 (The ADRD and ADDBLDR registers are not covered by the comparison function.)
- 2. Single scan mode must be used for matching or unmatching event output.
- 3. When temperature sensor or internal reference voltage is selected for window A, operation of window B is prohibited.
- 4. When temperature sensor or internal reference voltage is selected for window B, operation of window A is prohibited.
- 5. The same channel cannot be set for both window A and window B.
- 6. Single scan mode must be selected in order to use the buffer function. (The buffer function cannot be used in conjunction with double trigger mode.)
- 7. It is necessary to make settings such that high-side reference value ≥ low-side reference value.



4.1.4 Scan Conversion Time of 12-Bit A/D Converter

The scan conversion time of the 12-bit A/D converter differs on the RX111 Group and RX140 Group. The scan conversion time (t_{SCAN}) for single scan operation where the number of selected channels is n is shown below for each group. For details, refer to the description of analog input sampling and scan conversion time on the 12-bit A/D converter in the User's Manual: Hardware of the RX111 Group and RX140 Group, respectively, listed in 5, Reference Documents.

RX111: $t_{SCAN} = t_D + (t_{SPL} + t_{CONV}) n + t_{ED}$

RX140: $t_{SCAN} = t_D + (t_{DIS} \times n) + t_{DIAG} + (t_{CONV} \times n) + t_{ED}$

t_D: Start-of-scanning-delay time

tspl: Sampling time

tois: Disconnection detection assistance processing time

t_{DIAG}: Self-diagnosis A/D conversion processing time

tconv: A/D conversion processing time

ted: End-of-scanning-delay time

4.1.5 I²C Bus Interface Noise Cancellation

The RX111 Group incorporates analog noise filters for the SCL and SDA lines, but the RX140 Group does not have analog noise filters.

4.1.6 Port Direction Register (PDR) Initialization

PDR register initialization differs even with the same pin count.

5. Reference Documents

User's Manual: Hardware

RX111 Group User's Manual: Hardware Rev.1.30 (R01UH0365EJ0130)

(The latest version can be downloaded from the Renesas Electronics website.)

RX140 Group User's Manual: Hardware Rev.1.10 (R01UH0905EJ0110)

(The latest version can be downloaded from the Renesas Electronics website.)

Application Note

RX Family Design Guide for Migration between RX Family Differences in Package External Form (R01AN4591EJ)

(The latest version can be downloaded from the Renesas Electronics website.)

Technical Updates/Technical News

(The latest information can be downloaded from the Renesas Electronics website.)



Related Technical Updates

This application note reflects the content of the following technical updates:

TN-RX*-A153A/E

TN-RX*-A180A/E

TN-RX*-A193A/E

TN-RX*-A194A/E

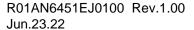
TN-RX*-A0147B/E

TN-RX*-A0230A/E

TN-RX*-A0224B/E

TN-RX*-A0241B/E

TN-RX*-A0258A/E





Revision History

		Description	
Rev.	Date	Page	Summary
1.00	Jun. 23, 2022	_	First edition issued

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

- 6. Voltage application waveform at input pin
 - Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
- 7. Prohibition of access to reserved addresses
 - Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
- 8. Differences between products
 - Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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